



FUTURE DETECTORS

M.C FOUZ - CIEMAT

9 SEPT 2024



LI - INTERNATIONAL MEETING ON
FUNDAMENTAL PHYSICS

TALK OBJECTIVES

The talk is oriented towards the **detectors for future e+e- Higgs factories**

BUT

synergies with HL-HLC present and future upgrades and other experiments

The talk aim to present

- **The most relevant requirements imposed to the detector to accomplish the expected physics program**
- **A fast overview of the different proposed detector concepts and the key differences**
- **A fast overview of the status of art and R&D on detectors**
- **A very,very, very, small touch on the Spanish groups activities (just few examples)**

**Even concentrating “only” on detectors for e+e- Higgs factories there is a large number of R&D ongoing all around the world
Some things will be described a bit, for others a brief comment or even I live them outside**

My view, my interpretation, my knowledge... my ignorance too

Baseline FCC-ee operation model,

Working point	Z, years 1-2	Z, later	WW	HZ	t \bar{t}	
\sqrt{s} (GeV)	88, 91, 94		157, 163	240	340-350	365
Lumi/IP (10^{34} cm $^{-2}$ s $^{-1}$)	115	230	28	8.5	0.95	1.55
Lumi/year (ab $^{-1}$, 2 IP)	24	48	6	1.7	0.2	0.34
Physics Goal (ab $^{-1}$)	150		10	5	0.2	1.5
Run time (year)	2	2	2	3	1	4
Number of events	5×10^{12} Z		10^8 WW	10^6 HZ + 25k WW \rightarrow H	10^6 t \bar{t} +200k HZ +50k WW \rightarrow H	

arXiv:2106.13885v2

Systematics are estimations

Observable	present value \pm error	FCC-ee Stat.	FCC-ee Syst.	Comment and leading exp. error
m_Z (keV)	91186700 \pm 2200	4	100	From Z line shape scan Beam energy calibration
Γ_Z (keV)	2495200 \pm 2300	4	25	From Z line shape scan Beam energy calibration
τ lifetime (fs)	290.3 \pm 0.5	0.001	0.04	radial alignment
τ mass (MeV)	1776.86 \pm 0.12	0.004	0.04	momentum scale
τ leptonic ($\mu\nu_\mu\nu_\tau$) B.R. (%)	17.38 \pm 0.04	0.0001	0.003	e/ μ /hadron separation
m_W (MeV)	80350 \pm 15	0.25	0.3	From WW threshold scan Beam energy calibration
Γ_W (MeV)	2085 \pm 42	1.2	0.3	From WW threshold scan Beam energy calibration
$\alpha_s(m_W^2)(\times 10^4)$	1170 \pm 420	3	small	from R_ℓ^W
$N_\nu(\times 10^3)$	2920 \pm 50	0.8	small	ratio of invis. to leptonic in radiative Z returns
m_{top} (MeV/c 2)	172740 \pm 500	17	small	From t \bar{t} threshold scan QCD errors dominate
Γ_{top} (MeV/c 2)	1410 \pm 190	45	small	From t \bar{t} threshold scan QCD errors dominate
$\lambda_{top}/\lambda_{top}^{SM}$	1.2 \pm 0.3	0.10	small	From t \bar{t} threshold scan QCD errors dominate
ttZ couplings	\pm 30%	0.5 - 1.5 %	small	From $\sqrt{s} = 365$ GeV run

FUTURE DETECTORS - M.C FOUZ

SOME PHYSIC EXPECTATIONS FOR FUTURE e+e- COLLIDERS

- Clearest environment than hadron colliders
No pileup, no underlying event E and p constraints...
- Huge number of events (e.g. 5×10^{12} Z vs 18×10^6 at LEP
108 WW pairs vs 8×10^3 W at LEP)

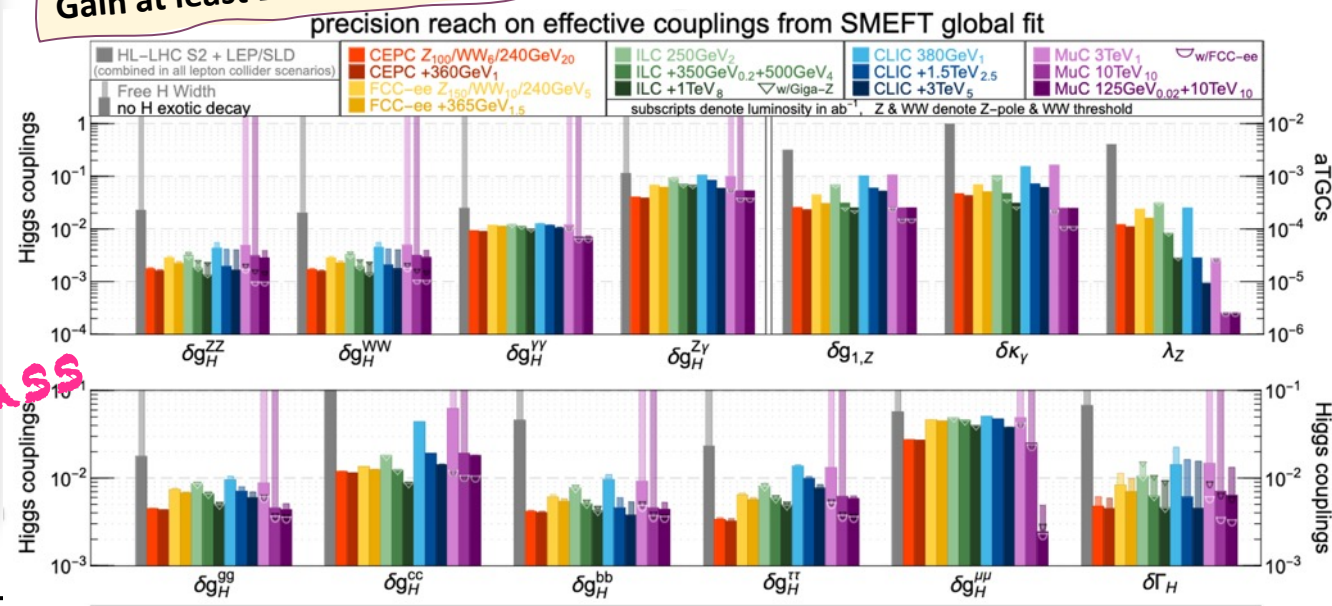


High precision can be achieved

To take full advantage of this conditions
DETECTORS WITH EXCELLENT PERFORMANCE ARE MANDATORY

Gain at least 1 order of magnitude

<https://arxiv.org/pdf/2206.08326>



SHOW MASS

(*) aTGCs = anomalous trilinear gauge couplings

DETECTOR CHALLENGES FOR FUTURE e+e- COLLIDERS

DETECTOR CHALLENGE

To achieve systematic uncertainties similar or smaller than the statistical

- Clearest environment than hadron colliders
No pileup, no underlying event E and p constraints...
- **Huge number of events** (e.g. 5×10^{12} Z vs 18×10^6 at LEP
108 WW pairs vs 8×10^3 W at LEP)

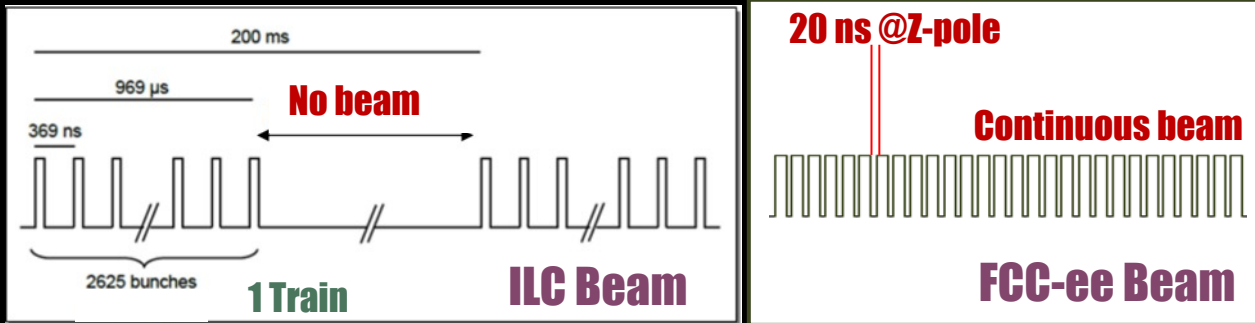
High precision can be achieved

SOME PERFORMANCE REQUIREMENTS DRIVEN BY PHYSICS

Momentum	$\sigma_{p_t}/P^2_T \sim 3-4 \times 10^{-5}$ (~7 μm single hit resolution) (~1/10 of LEP)
Angular resolution	< 0.1 μrad for 45 GeV muons
Impact parameter	$\sigma_{d_0} = 5 \oplus 15 (p \sin \theta^{3/2})^{-1} \mu\text{m}$ (~3 μm single hit resolution) (b and c tagging capability)
E.M resolution	< 10 – 15 % \sqrt{E} (with low constant term)
Jet energy resolution	~30% \sqrt{E} (~ a factor 2 better than present)
Particle Identification (PID)	Excellent lepton and photon ID (e/π , μ/π , γ/π^0), π/K , K/p separation (heavy flavor studies)... for a broader momentum range for e, μ and hadrons to improve tagging, jet energy...
Hermetic coverage	will play an important role
Precise timing	
	Improve PID
	Beam-induced background rejection
	Pile-up rejection
	Improve calorimeter/tracker reconstruction

MAIN DIFFERENCES BETWEEN CIRCULAR AND LINEAR e^+e^- COLLIDERS IMPACTING ON DETECTORS (I)

Beam structure



Continuous beam has implications on power, rates, readout...

ILC experiments uses power pulsing
(electronics off between trains)
=> Reduction of power consumption a factor $\mathcal{O}(10)$

Luminosity. FCC-ee running at Z pole (Tera-Z vs Giga-Z)

@ Z-pole: $L \sim 1.8 \times 10^{36}/\text{cm}^2$: Z-pole, physic event rates up to 100 kHz. (pile up of 2×10^{-3})

Implication on detectors, electronics, DAQ: response time, time resolution, size of event, data handling....

Huge statistic \rightarrow Systematic control down to $\sim 10^{-5}$ level

Excellent control of acceptances needed

Luminosity measurements $\sigma(L)/L = 10^{-4}$ (for low angle Bhabha events)

Constraints on design (including mechanics of Endcap Calorimeter and LumiCal)

MAIN DIFFERENCES BETWEEN CIRCULAR AND LINEAR e+e- COLLIDERS IMPACTING ON DETECTORS (II)

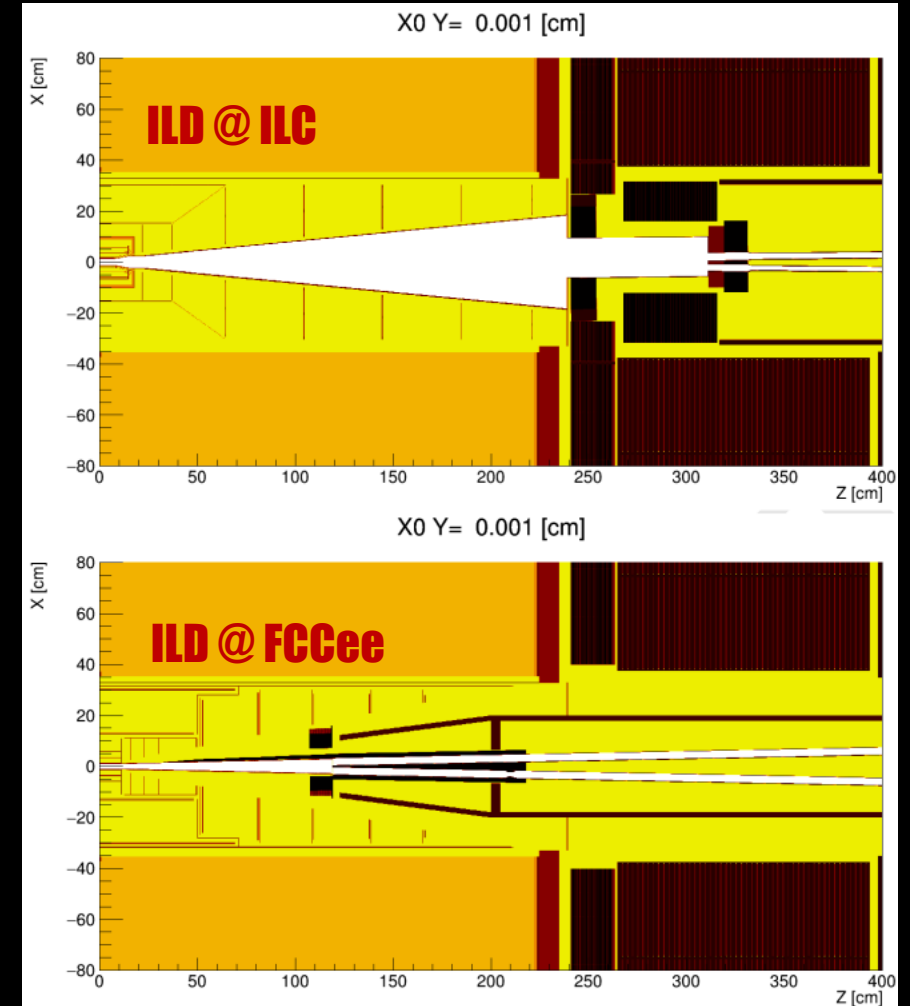
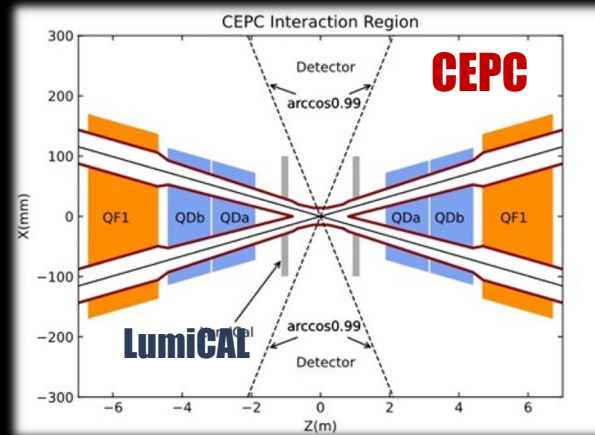
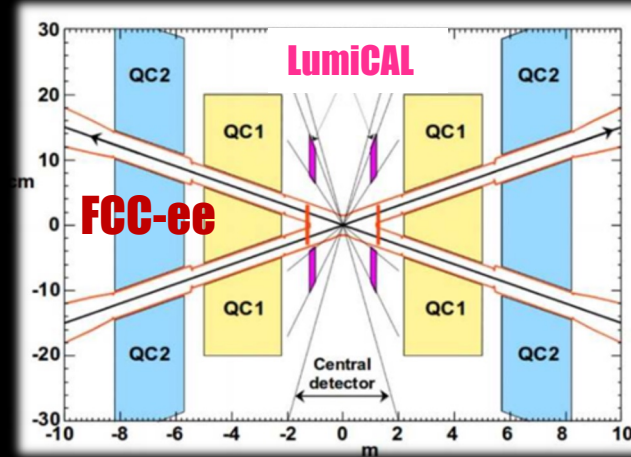
Daniel Jeans

Machine Detector Interface (MDI)

Crossing angles at interaction Point (mrad)		L* (meters)	
ILC	14	ILC	4.1
CLIC	16.5 -20	CLIC	6
FCC-ee	30	FCC-ee	2.2
CEPC	33	CEPC	2.2

Circular machines:

- Last focusing magnet (at L*) **INSIDE** the detector volume (also the LumiCal at 1m from IP – vs 2.5m)
- B field limited to 2T at Z-pole operation (vs ~3.5T for linear) → Larger tracker volume



Lower tracker acceptance for FCCee vs ILC

$\theta < 100$ mrad reserved to magnets and instrumentation + Lumical (up to 150 mrad)
Forward tracker limitation > 10 deg.

MAIN DIFFERENCES BETWEEN CIRCULAR AND LINEAR e+e- INTERACTION REGION SUMMARY

	FCC-ee	CEPC	ILC	CLIC
L* (Δz between IP and first)	2.2 m	2.2 m	4.1 m	6 m
Position of final quadrupole	Inside detector	Inside detector	Outside detector	Outside detector
LumiCal position	z=1m, ~50-100 mrad (Constrained by compensating solenoid)	z~0.95~1.11m 26-105 mrad (fiducial volume 53-79 mrad)	z=2.5m, 33-80 mrad	z=2.5m, 39-134 mrad
Tracker acceptance	Down to ~9 degrees (defined by luminometer)	Down to ~8 degrees	Down to ~6° (defined by conical beam pipe)	Down to ~7° (defined by conical beam pipe)
Inner beam pipe radius	10 mm	10 mm	16 mm	29.4 mm
Crossing angle	30 mrad	33 mrad	14 mrad	20 mrad
Main solenoid B field	2T	3T (2T at Z pole)	3.5-5T	4T

Constraints from accelerators to future e+e-factory experiments - Giovanni Marchiori -

COORDINATED R&D DETECTOR EFFORTS WORLDWIDE - EUROPE VIEW - ROADMAP

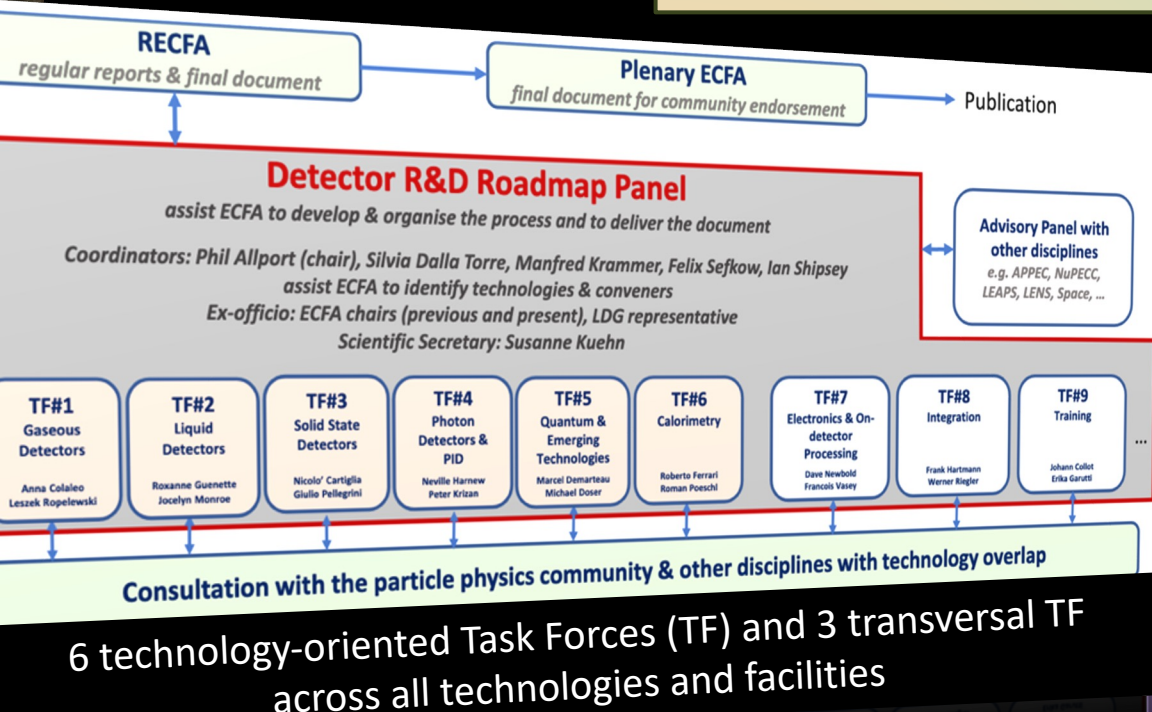
European Strategy for Particle Physics - Update 2020



C. The success of particle physics experiments relies on innovative instrumentation and state-of-the-art infrastructures. To prepare and realise future experimental research programmes, the community must maintain a strong focus on instrumentation. **Detector R&D programmes and associated infrastructures should be supported at CERN, national institutes, laboratories and universities. Synergies between the needs of different scientific fields and industry should be identified and exploited to boost efficiency in the development process and increase opportunities for more technology transfer benefiting society at large. Collaborative platforms and consortia must be adequately supported to provide coherence in these R&D activities. The community should define a global detector R&D roadmap that should be used to support proposals at the European and national levels.**



Detector Roadmap



Identification of R&D topics and Timeline

Approved by CERN Council Dec 2021

aim to establish the DRD collaborations which should start work in January 2024, with a ramp-up of resources through 2024/2025, reaching a steady state by 2026.

Detector Roadmap implementation Approved Sep. 2022



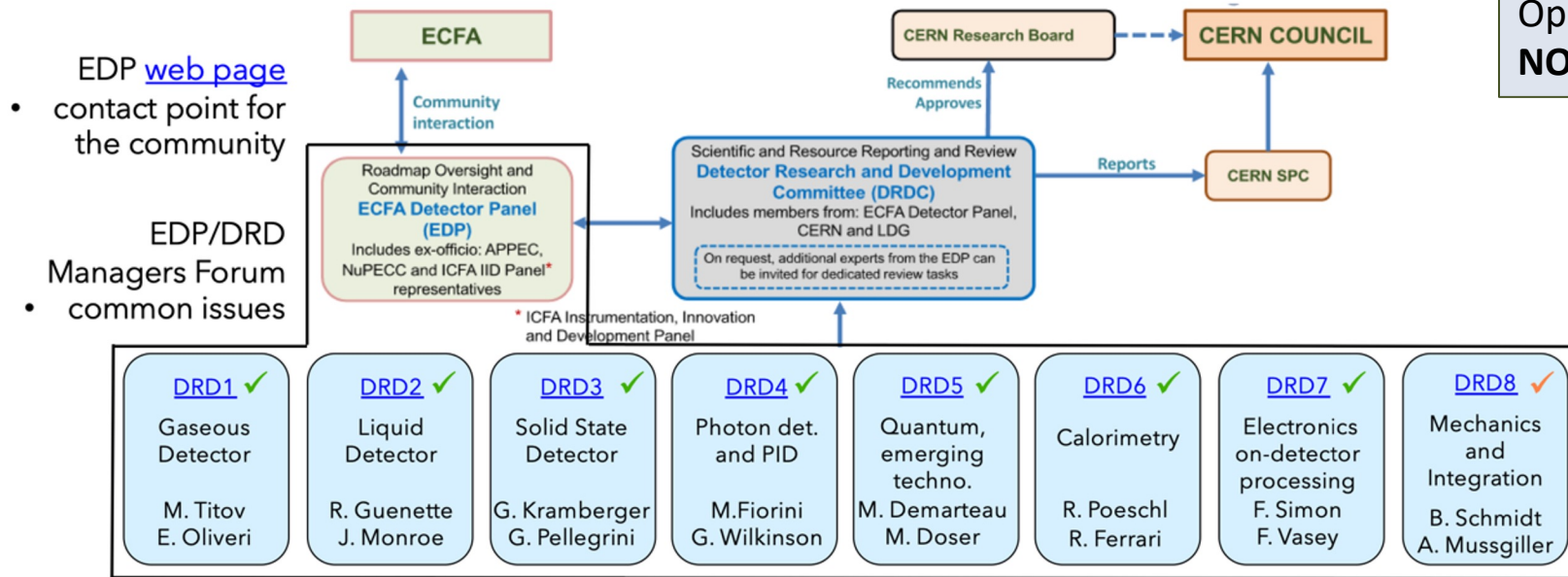
<http://cds.cern.ch/record/2784893>

SEP. 2024

COORDINATED R&D DETECTOR EFFORTS WORLDWIDE - EUROPE VIEW – DRD COLLABORATIONS

New DRD collaborations hosted at CERN ([framework](#)) follows [general conditions](#) for execution of experiments at CERN

Open to collaborators all over the world
NO restricted to Europe



- EDP [web page](#)
- contact point for the community
- EDP/DRD Managers Forum
- common issues

✓ Approved by CERN RB*, ✓ DRD8 Lol submitted to DRDC, proposal aims end-2024

DRDC [wep page](#) and presentations of DRDs at [open sessions](#)

From D. Contardo (IP2I)
ECFA highlights and DRD collaboration progress
FCCee week. San Francisco June 2024

* approvals cover a period of three years - to be renewed

COORDINATED R&D DETECTOR EFFORTS WORLDWIDE - US VIEW

Recommendation 4: Support a comprehensive effort to develop the resources—theoretical, computational, and technological—essential to our 20-year vision for the field. This includes an aggressive R&D program that, while technologically challenging, could yield revolutionary accelerator designs that chart a realistic path to a 10 TeV pCM collider.

Investing in the future of the field to fulfill this vision requires the following:

a. Support vigorous R&D toward a cost-effective 10 TeV pCM collider based on proton-muon

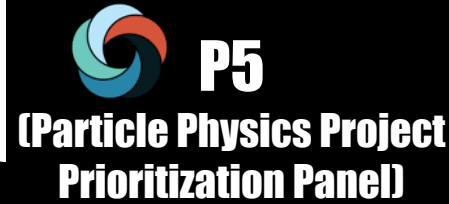
d. Invest in R&D in instrumentation to develop innovative scientific tools (section 6.3)

6.3

Detector Instrumentation

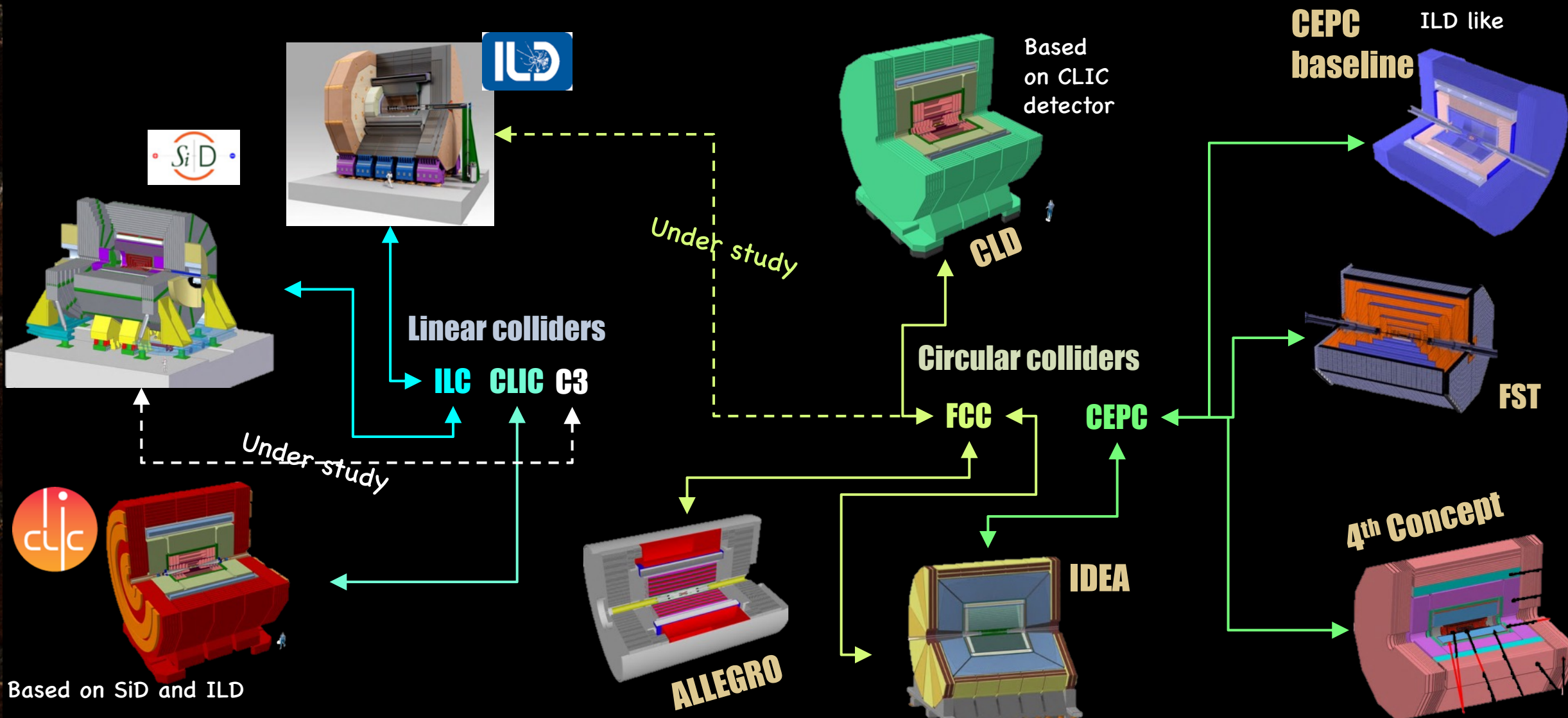
The field of particle physics is at an exciting juncture where current detector instrumentation technologies have pushed the boundaries of sensitivity and scalability. Whereas modest

The particle physics community has identified the need for stronger coordination between the different groups carrying out detector R&D in the US. We strongly support the R&D collaborations (RDCs) that are being established and will be stewarded by the Coordinating Panel for Advanced Detectors, overseen by the APS Division of Particles and Fields. The RDCs are organized along specific technology directions or common challenges and aim to define and follow roadmaps to achieve specific R&D goals. This coordination will help to achieve a more coherent detector instrumentation program in the US and will help to avoid duplication while addressing common challenges. International collaboration is also crucial, especially in cases where we want to have technological leadership roles. Involvement in the newly established detector R&D groups at CERN is encouraged, as are contributions to the design and planning for the next generation of international or global projects. Targeted future collider detector R&D, such as for Higgs factories or a muon collider, is covered in section 6.5



RDC#	TOPIC
1	Noble Element Detectors
2	Photodetectors
3	Solid State Tracking
4	Readout and ASICs
5	Trigger and DAQ
6	Gaseous Detectors
7	Low-Background Detectors
8	Quantum and Superconducting Sensors
9	Calorimetry
10	Detector Mechanics
11	Fast Timing

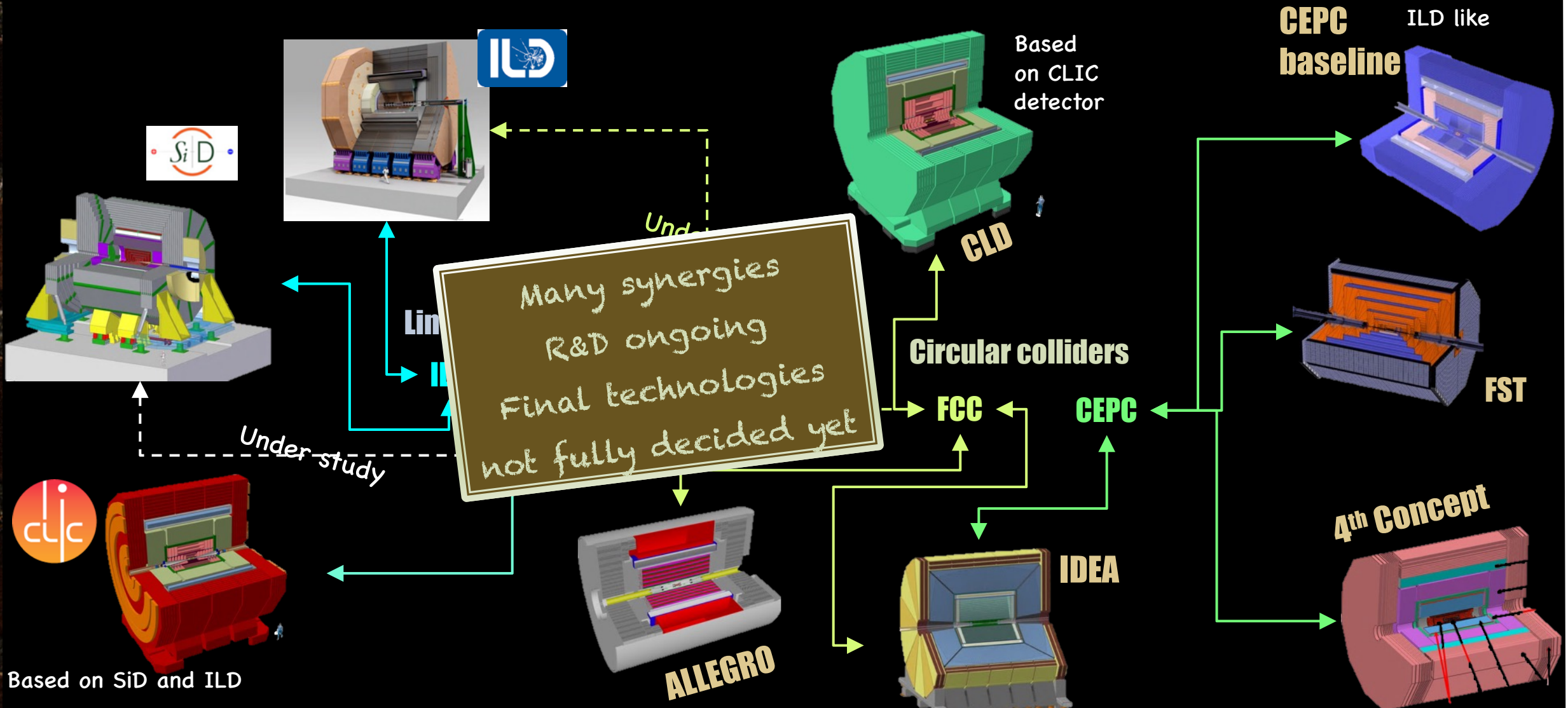
PROPOSED DETECTOR CONCEPTS



Based on SiD and ILD



PROPOSED DETECTOR CONCEPTS



VERTEX AND TRACKER DETECTORS – SUMMARY REQUIREMENTS

- **Excellent position resolution**

The most demanding is for **primary and secondary vertex**, as for b- and c-tagging capabilities ($\sim 3\mu\text{m}$ single layer),
lifetime measurements (τ lifetime to sub- 10^{-5}), B physics
First layer as close to IP as possible

- **Very low material budget**

To reduce the multiple scattering for Pt resolution & particle flow calorimeter measurements
(limits photon conversions and hadronic interactions)
Challenge for the detector technology itself and the associated mechanics (supports, services..)

- **Low power consumption on-detector electronics to minimize/avoid the cooling needs**

More important for circular machines since power pulsing cannot be applied
Requirements: 50 mW/cm² (vertex) / 150 mW/cm² (tracker)

- **Time resolution $\mathcal{O}(1\ \mu\text{s})$ [$\mathcal{O}(\text{ns})$ for CLIC]**

Benefits of precise timing <100 ps under study but not mandatory.

Could be implemented on the tracker or in a dedicated layer.

Enhanced background/backscatter rejection

4D tracking

particle ID by Time-of-Flight for heavy-flavour physics <30 ps / 2m for K/pi/p separation up to 3 GeV

- **High efficiency crucial for calorimeter measurements (Particle flow)**

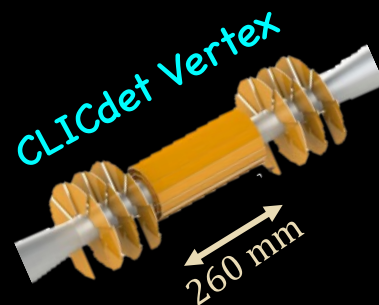
VERTEX AND TRACKER DETECTORS AT THE DIFFERENT CONCEPTS

VERTEX

All use **pixel silicon detectors**

~ 5-6 layers @Barrel and up to 6 @endcap.
single or double layer

Pixel size $\leq 25\mu\text{m}$



TRACKER

Two different approaches

- **Full silicon system**

Strips or large pixels

- Gaseous detector surrounded by a layer of **Silicon detector**

Several gaseous detectors options TPC
Drift Chambers

TRACKER OPTIONS

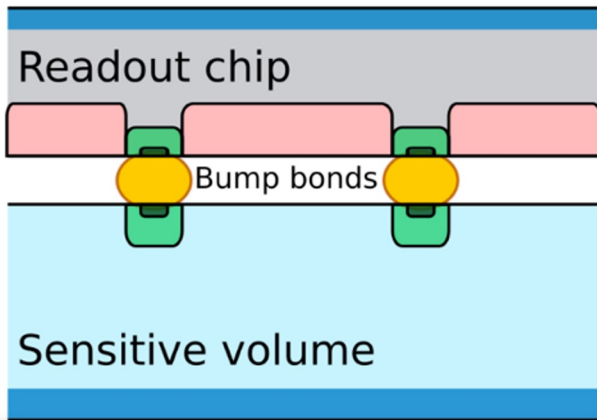
SiD	Silicon Strips
CLICdet	Silicon Pixels
CLD	Silicon Pixels
ALLEGRO	Drift chambers + Silicon Strips or Silicon Pixels
CEPC baseline	TPC + Silicon Strips or Silicon Strips
ILD	TPC + Silicon Strips
IDEA	Drift Chamber + Silicon Strips
4th Concept	TPC + Silicon Strips or Drift Chamber + Silicon Strips

VERTEX AND TRACKING SILICON DETECTORS

HYBRID

Sensor and readout electronics
in **two** separate chips
Connected by "bump bonding"

Hybrid sensor sketch



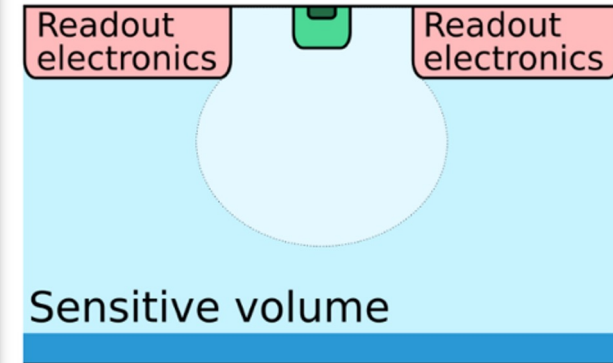
Separate optimization of sensor and readout
On-pixel functionality using mixed-mode CMOS circuits
(powerful processing – fast)

Two main categories

MONOLITHIC

Sensor and readout electronics
in **SAME** chip

Monolithic sensor sketch

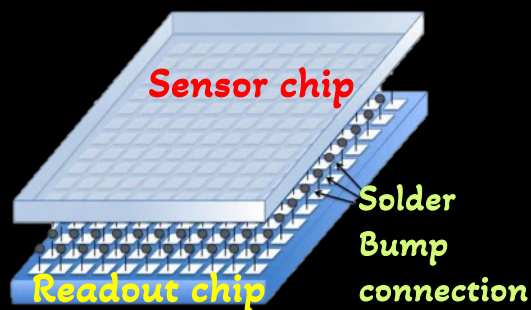
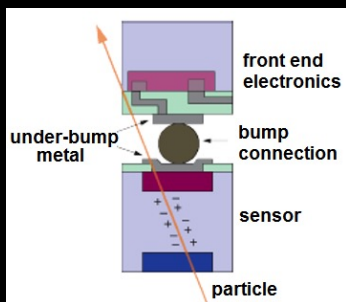


Lower material budget,
reduced complexity and production cost
No bump bonding → Smaller pixel size (few μm^2)

Less sophisticated readout electronics

VERTEX AND TRACKING SILICON DETECTORS - HYBRID

Some examples of options under development



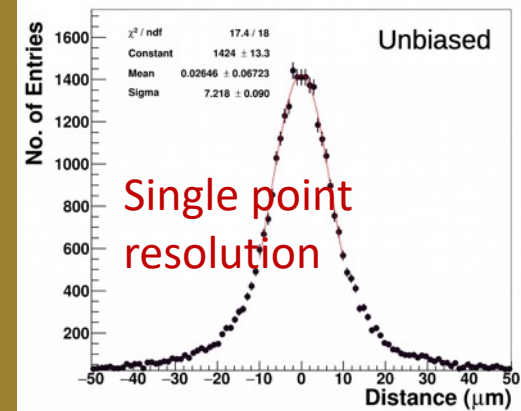
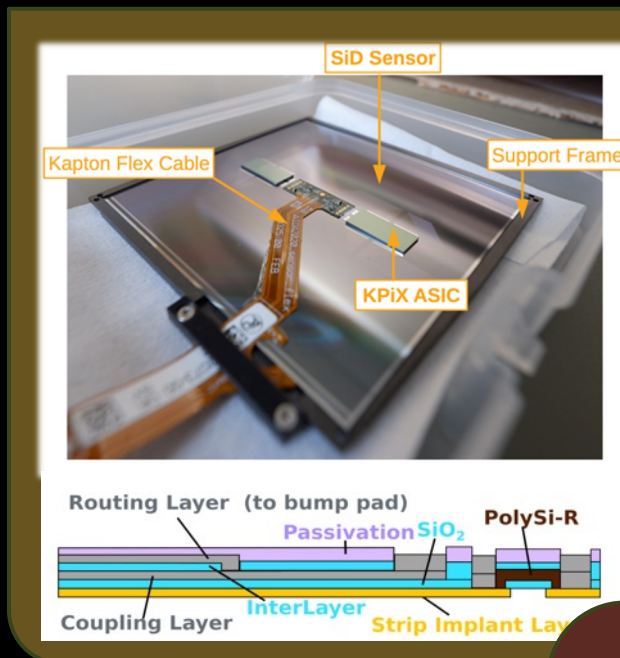
Sensor and readout electronics in **two** separate chips
Connected by "bump bonding"

Concerns: Material Budget, interconnection

Different interconnect technologies are under study for future-collider detectors:

- Single-die bump-bonding process
- Hybridization with Anisotropic Conductive Films (ACF)

For picosecond timing → **LGAD**
(Low Gain avalanche Photodiode)



https://indico.cern.ch/event/995633/contributions/4259345/attachments/2210031/3740113/LCWS_2021.pdf

10 x 10 cm²

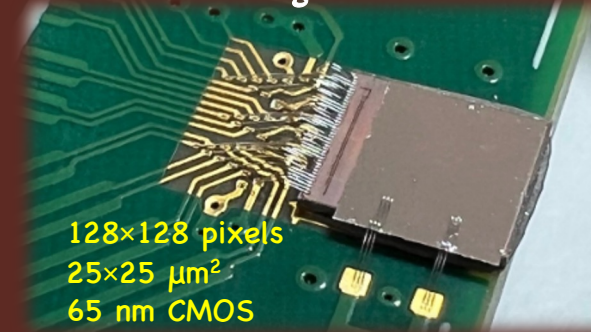
320 μm Thickness → 0.3% X₀

Pitch 25 μm → hit resolution ~7.2 μm

92 mm strip length

An integrated (bump-bonding) pitch adapter and digital readout **ASIC: KPiX**

CLICpix2 ASIC bump-bonded to an active edge silicon sensor

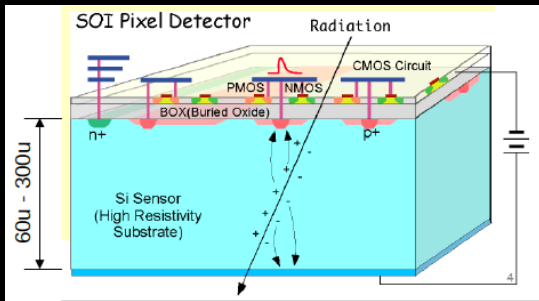


VERTEX AND TRACKING SILICON DETECTORS - MONOLITHIC

Different types are under development

MONOLITHIC Sensor and readout electronic in the same chip

SOI (Silicon-on-Insulator)

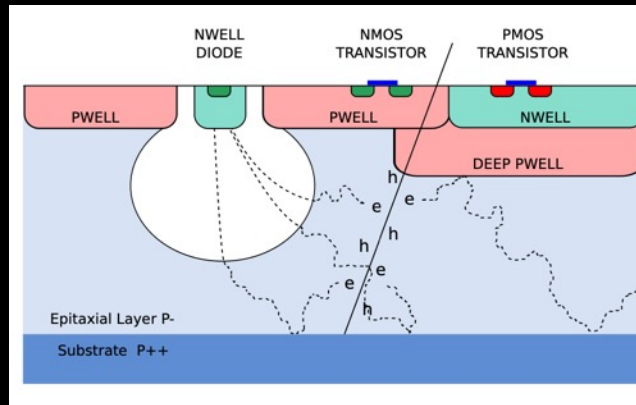


NIMA 623(2010)186

Layer structure: thin layer of silicon (SiO_2) placed on top of an insulating material

Thin and fast, can be fully depleted

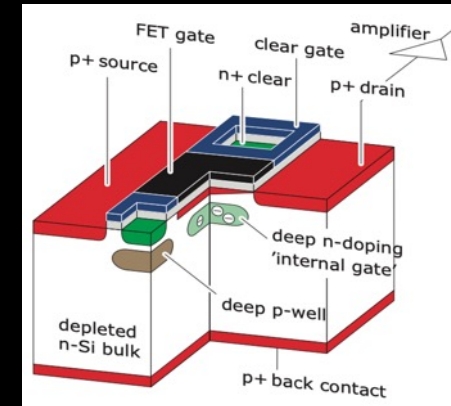
CMOS – MAPS & DMAPS
(MAPS= Monolithic Active Pixel Sensor)



(CMOS=Complementary Metal-Oxide-Semiconductor) silicon pixel)

SEMI-MONOLITHIC

DEPFET - Depleted field-effect transistor



Amplification integrated but subsequent processing in an external ASIC
Large signal even for thin detectors
Fast signal rise time (ns)

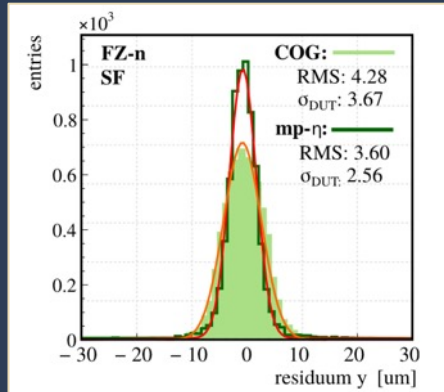
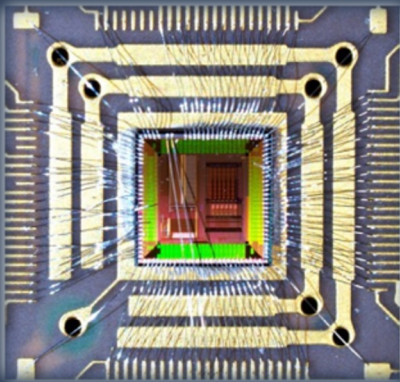
MONOLITHIC SILICON DETECTORS – FEW EXAMPLES OVERVIEW

There are many developments on going, here some examples. Many advances last years but still R&D needed

SOI (Silicon-on-Insulator)

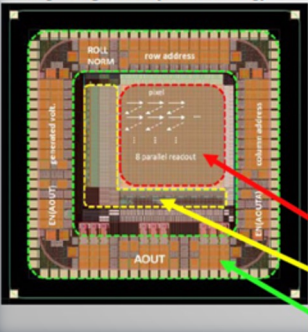
Cracow SOI Chips

(*) COG & mp-n are diff. algorithms



30x30 μm^2 pixel size <https://doi.org/10.1016/j.nima.2020.164897>

chip layout (3mm-sq)



FPIX2
resolution demonstrator
8 x 8 μm^2

FPIX2 DSOI : Double silicon-on-insulator

DSOI = 2 layers of Si separated by insulator

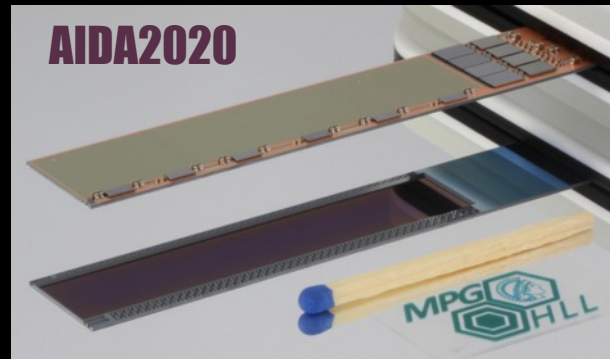
PIXEL

DECODER

I/O

DEPFET

BELLE II vertex detector and ILC central vertex



DEPTFET all-silicon ladder for Belle II
Metal layer on top of the sensor
Thinner area visible on the mirror image underneath the ladder

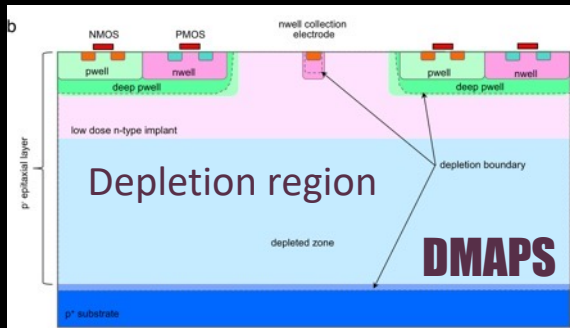
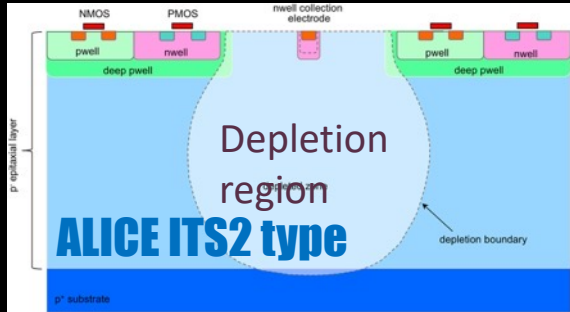


MONOLITHIC SILICON DETECTORS – FEW EXAMPLES OVERVIEW

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MAPS/DMAPS

DMAPS = Depleted MAPS



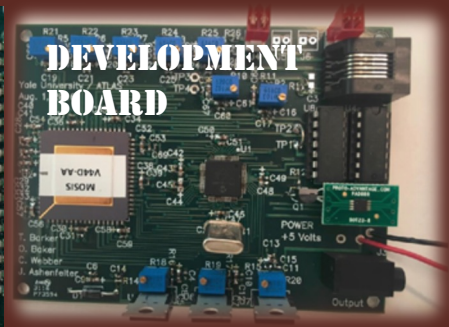
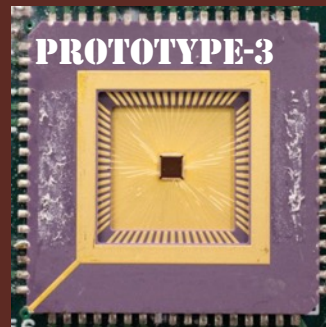
Depletion region increase when reverse bias is increased.
Difficult to expand laterally

DMAPS: Faster, higher charge collections, better S/N, better radiation tolerance, less cross-pixel charge

Chronopixel

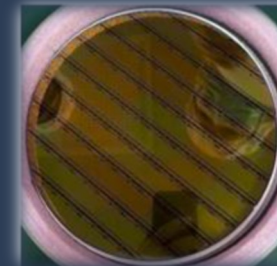
Time-stamping capability
Hit accompanied by a time tag (precision to assign BX of ILC)
occupancy reduction to $<10^{-4}$ per pixel

25x25 μm^2 pixel size, 90 nm technology
Zero suppression
Digital readout \rightarrow simplifies electronics

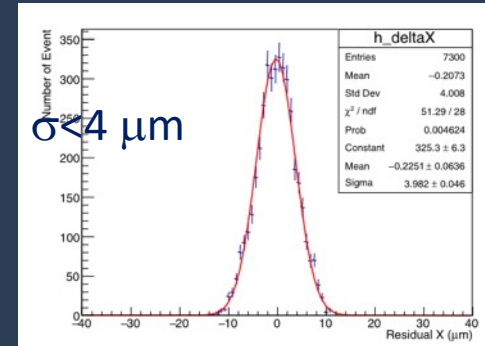


TaichuPix

25 x 25 μm^2 pixel



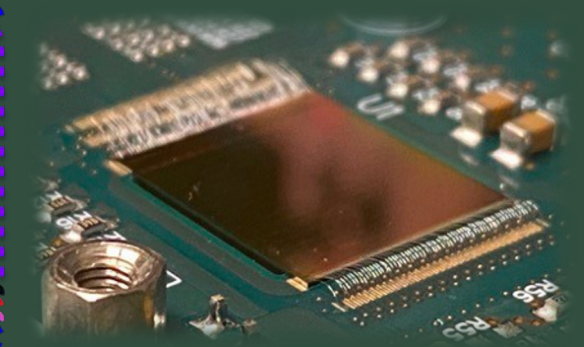
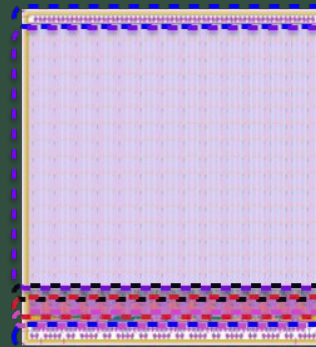
For vertex at CEPC baseline



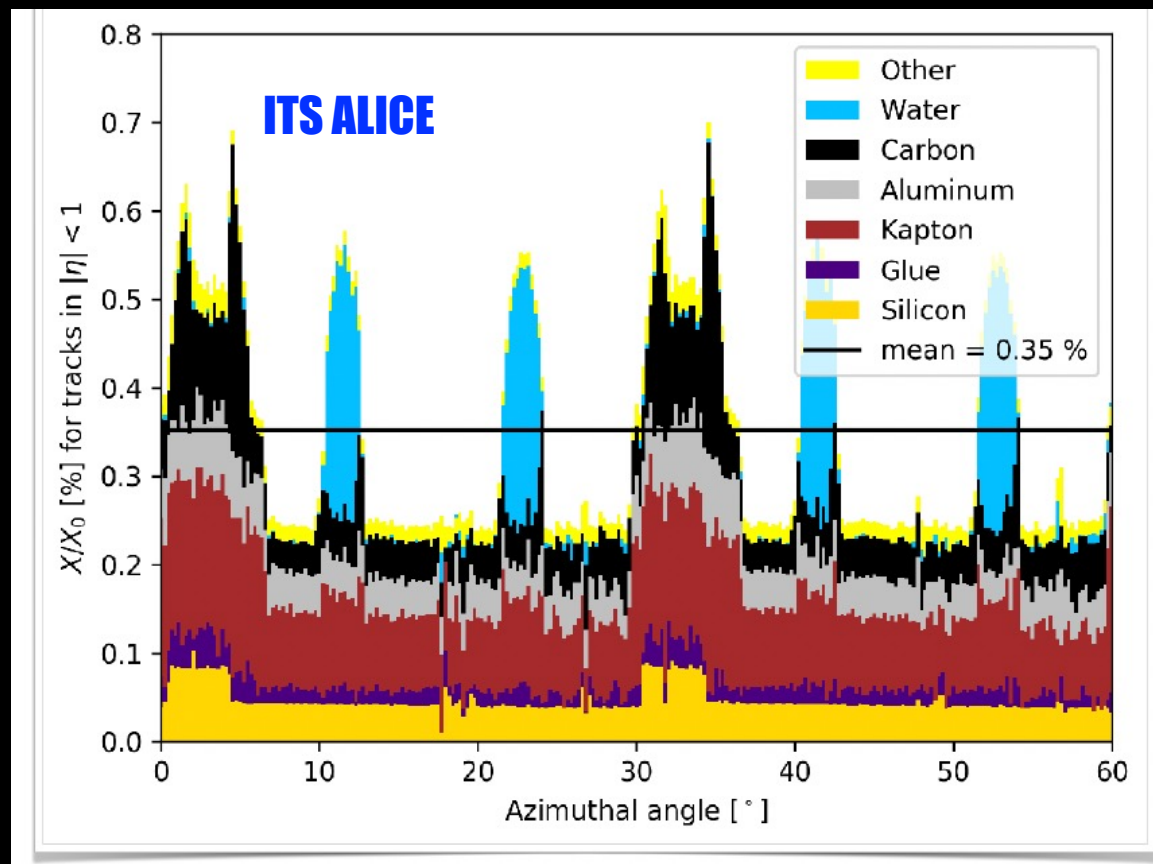
ARCADIA

Fully depleted
Lfoundry 110nm CMOS
25x25 mm² pixel size

For IDEA

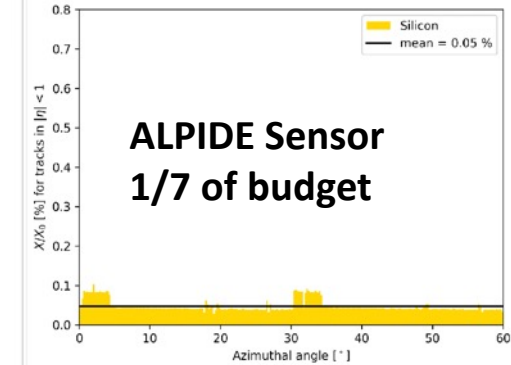
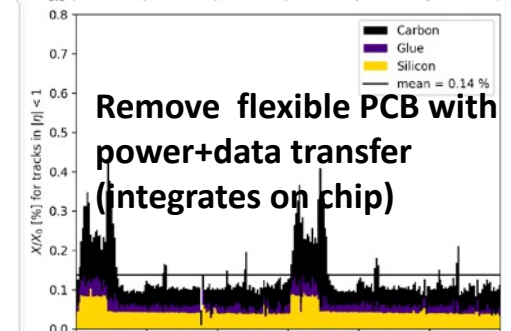
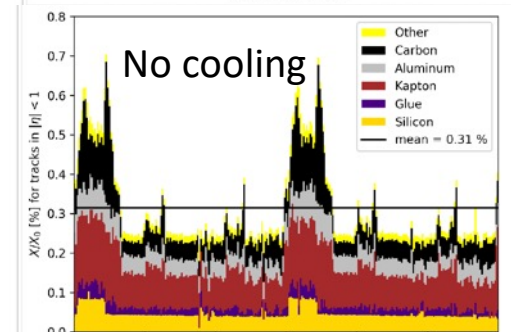
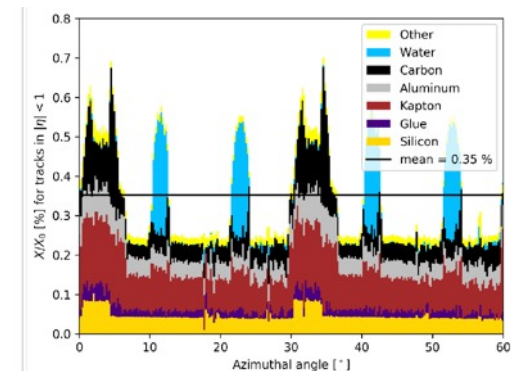


MATERIAL BUDGET OPTIMIZATION - COMPONENTS



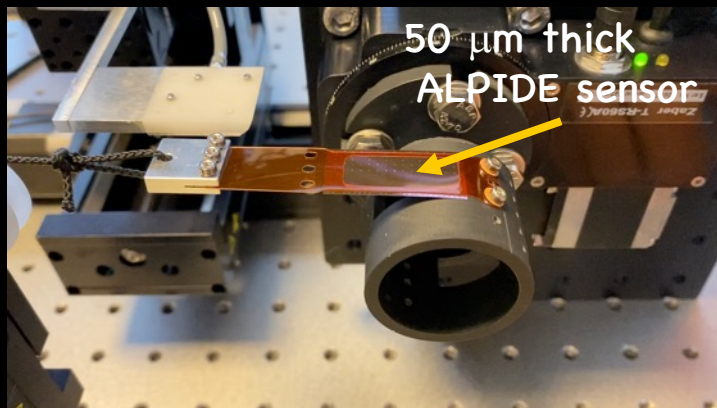
Material Budget is dominated by cooling, supports, and cabling

How to reduce it? Taking a look to the approach for the ALICE ITS3

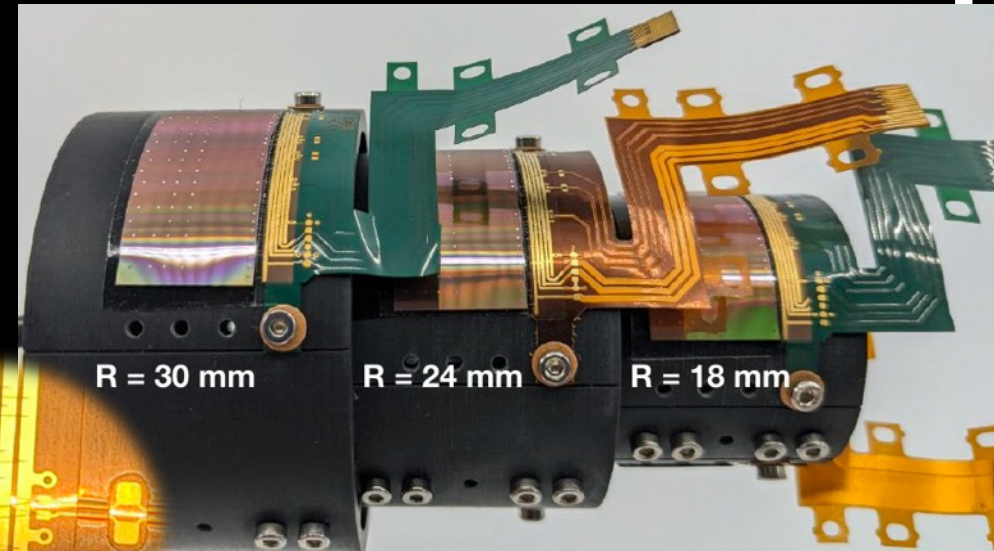
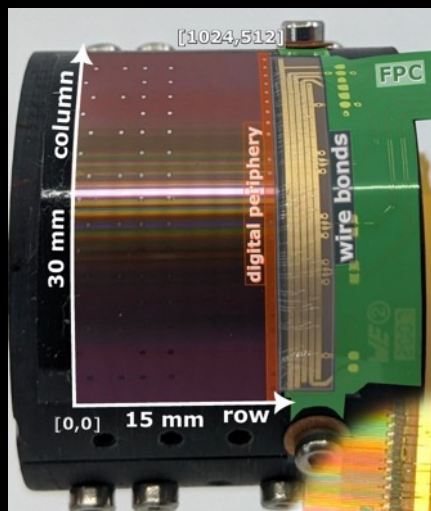
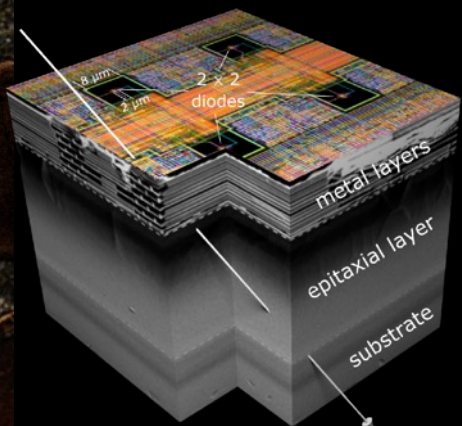


MATERIAL BUDGET OPTIMIZATION – BENT SENSORS – ALICE ITS 3

Silicon is flexible



Flex embedded sensors



MATERIAL BUDGET OPTIMIZATION – BENT SENSORS & STITCHING

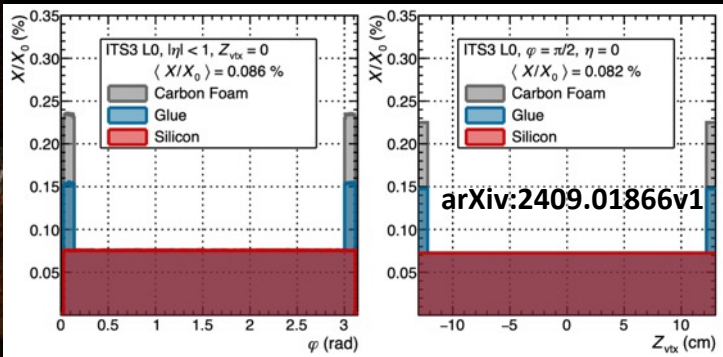
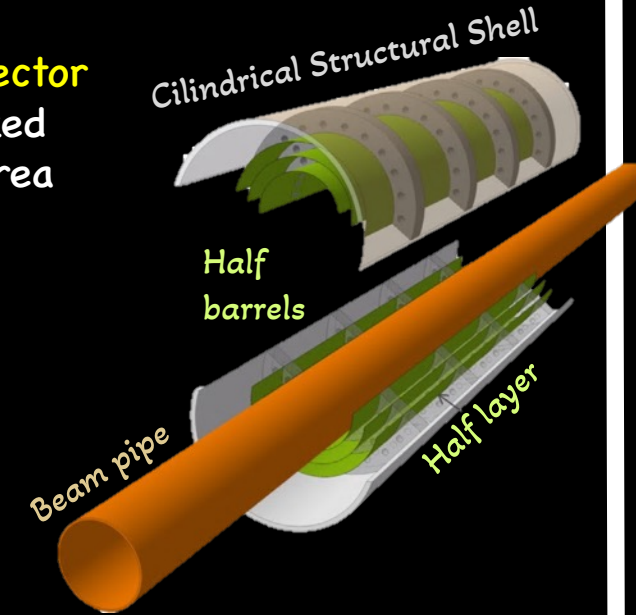
– ALICE ITS 3

Replace 3 innermost layers of the ITS2 with a new detector
 Cooling and mechanical structures are minimized
 Silicon sensors only component in the active area

Radius innermost layer reduced from 22mm to 18mm

Cooling by air flow → Power limit 20mW/cm²

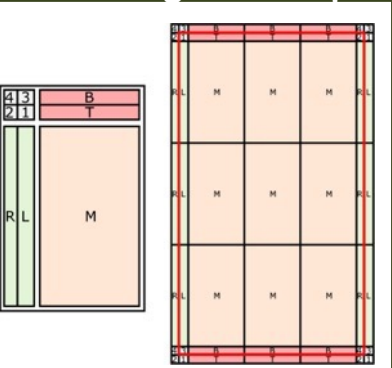
Power supply and transfer data cannot be on the chip
 ==> Circuits located at the short edges of the chip



Reduction of the radiation length per layer
 from 0.35% X₀ to 0.75%X₀ layer
 More uniform distribution

Use Stitching!!

Stitching technique

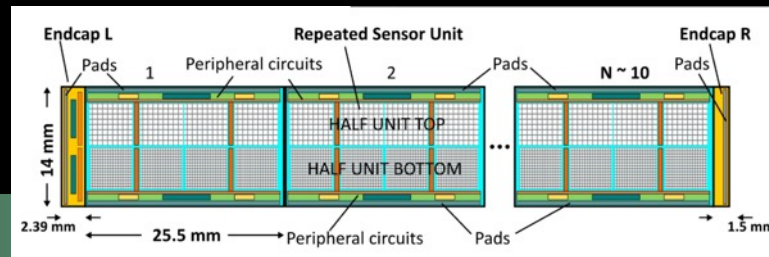


Stitched sensors

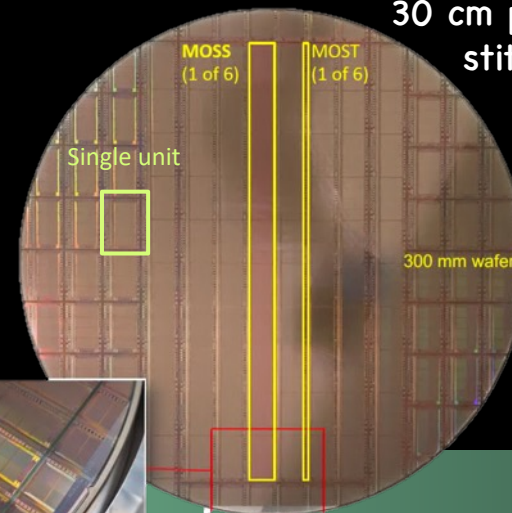
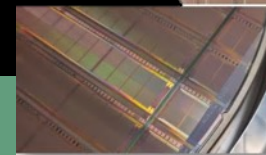
MOSS – Monolithic Stitched sensor chip

MOST – MOSS with Timing

MOSS design 65nm MAPS



Engineer run-1



30 cm pad wafer using stitching on middle

MOSS
 259×14 mm²
 6.72 Mpixels

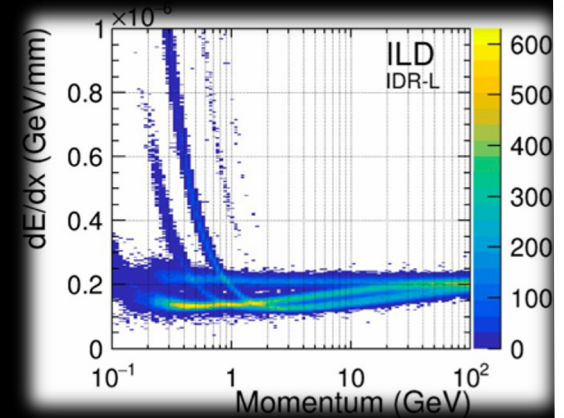
TRACKING – GASEOUS VS SILICON DETECTORS

Gaseous detectors → lower material budget
 → less multiple scattering

Gaseous detectors can provide dE/dx
 ==> TPC strength

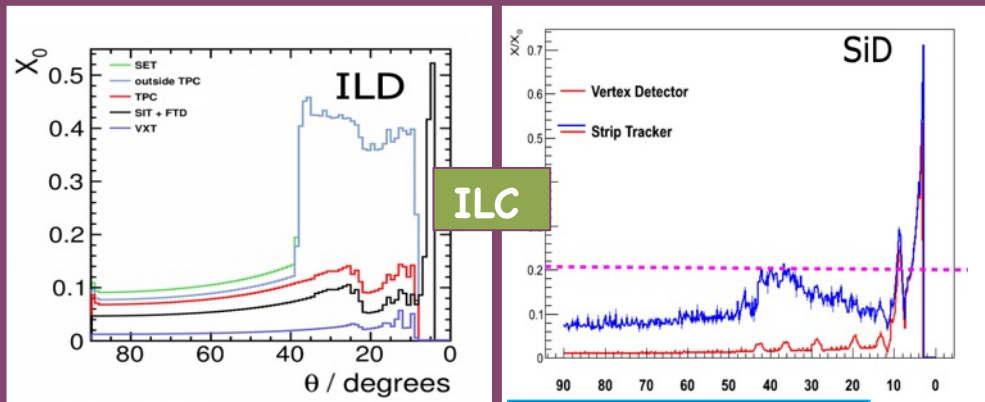
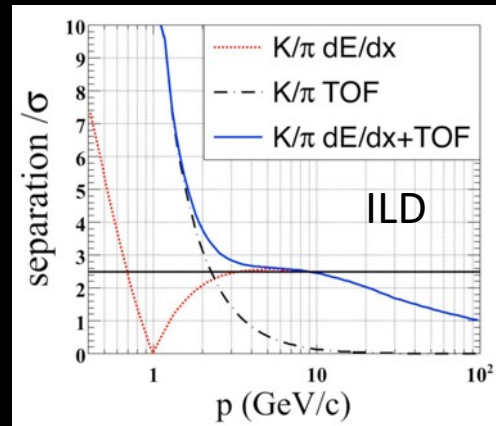
PID capabilities

Up to 220 points at ILD TPC



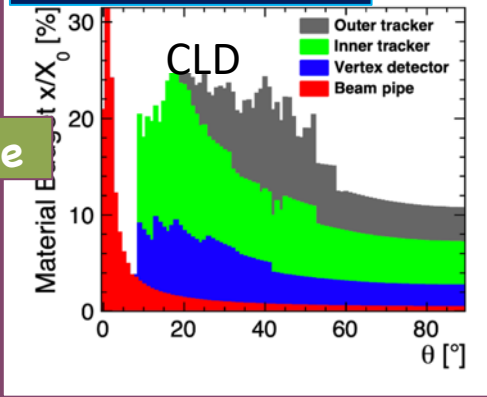
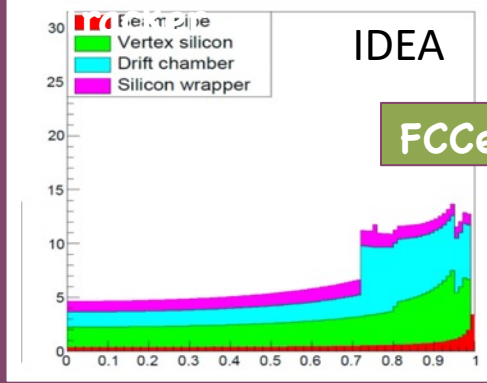
arXiv:2202.03285v1

Kaon identification
 Flavour physics (up to 40 GeV)
 Key for strange tagging

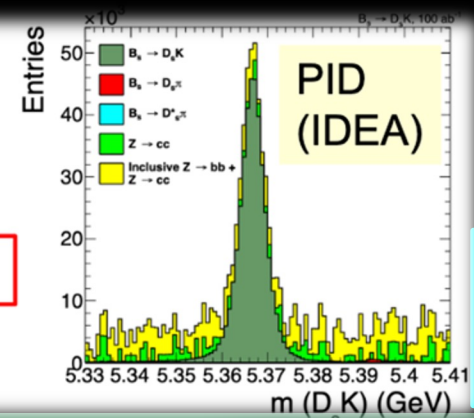
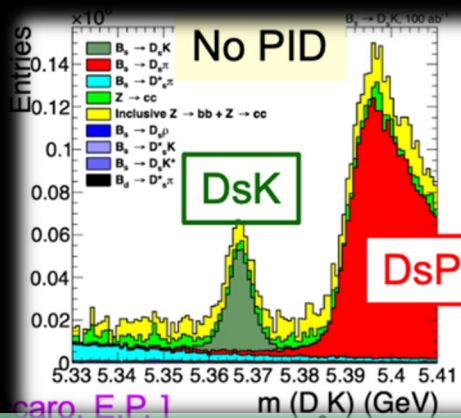
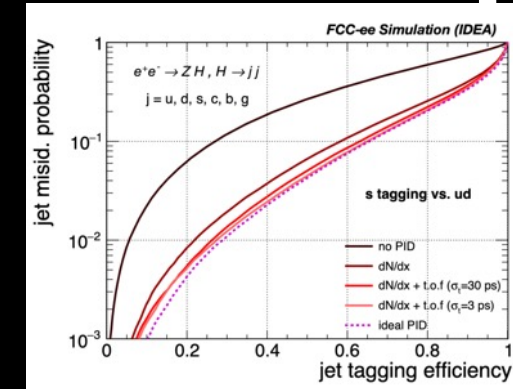


Gaseous

Silicon tracker



Notice the different plot scales



CP-violation studies
 distinguish
 $B^0_s \rightarrow D_s K$ from $B^0_s \rightarrow D_s K \pi$

TRACKING - TPC

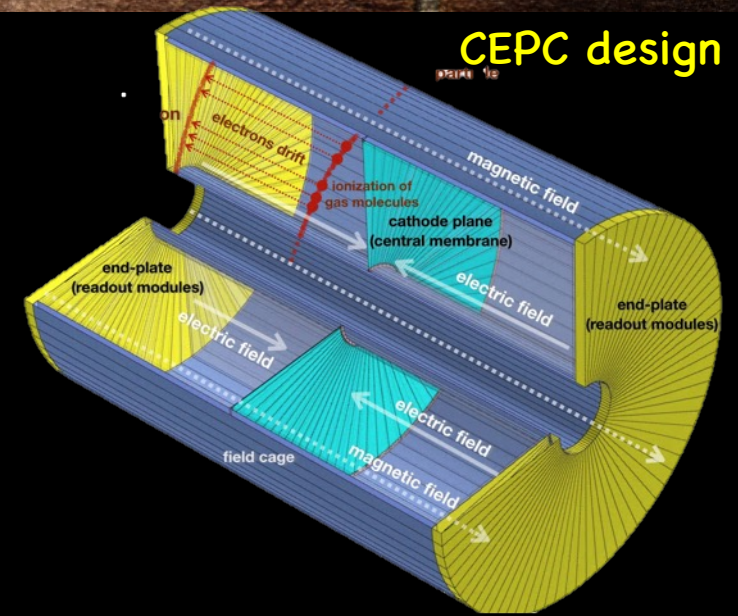


Proposed for ILD, CEPC Baseline and 4th Concept

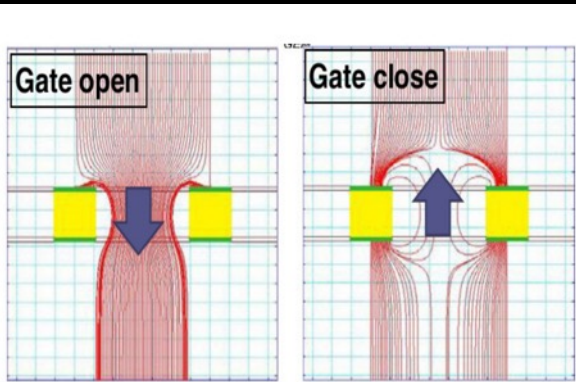
No clear its capabilities to cope with the Z-pole conditions for circular colliders

Several studies ongoing at LC-TPC and ILD collaborations

The concern is the **ion back flow** that at Z pole could increase too much as for producing **field distortions** on the drift region → **more R&D needed**

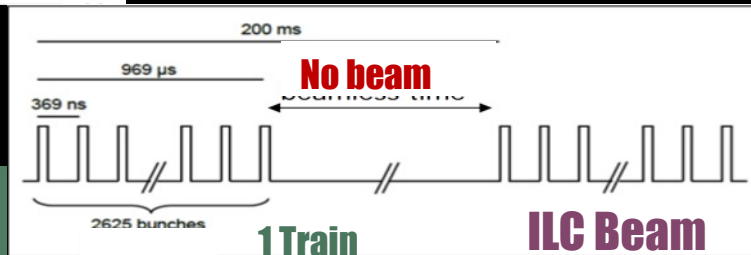


Also happens in **ALICE TPC** with the **GEM readout upgrade for Run 3**
 Expected 1% ions drifting back and $\mathcal{O}(5-10 \text{ cm})$ distortions
 Effects corrected by software with proper calibrations going down to $\mathcal{O}(100\mu\text{m})$



NIM A918 (2019) 41-53

ILC gating scheme using GEM
 Gap opens 50 μs before the first bunch and closes 50 μs after



Gating cannot be used at circular colliders due to the continuous beam

TRACKING - TPC SENSOR OPTIONS

Different options for the readout have been studied along years

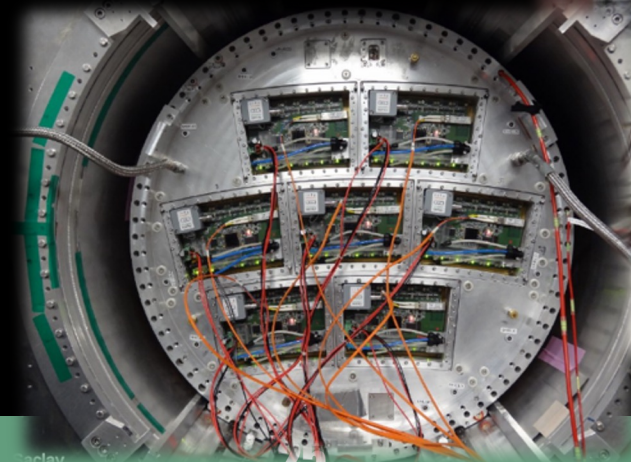
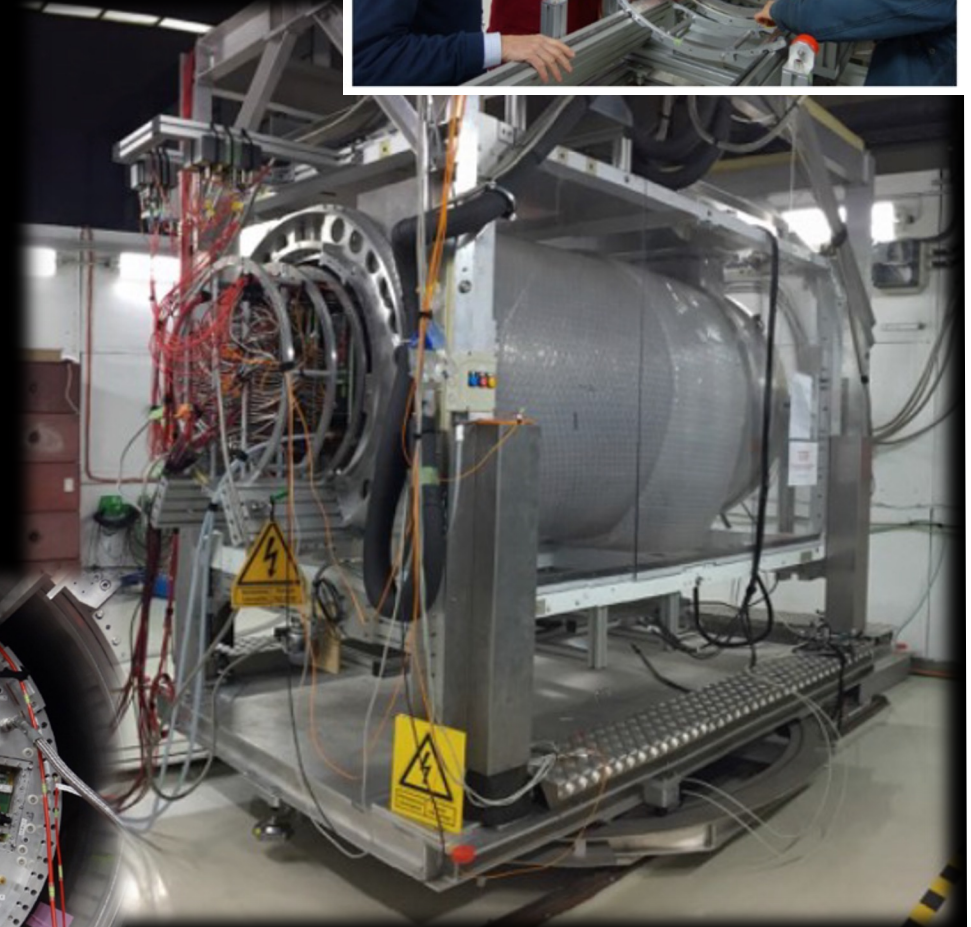
A setup available at DESY allows tests with beam with different detectors

GEM

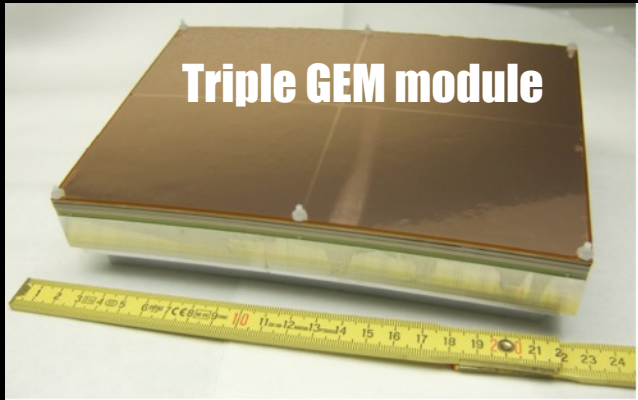
Resistive MICROMEGAS

GRIDPIX

New devices combining GEM and Micromegas have been also designed to control the ion back flow



TRACKING - TPC SENSOR OPTIONS



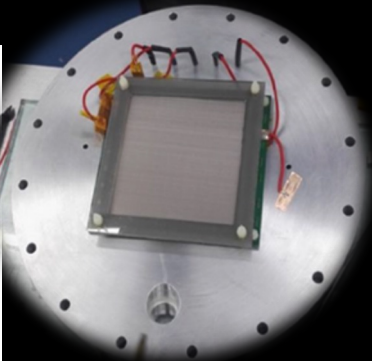
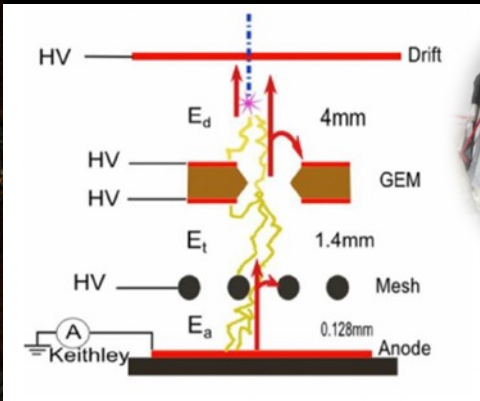
MMGEM

Diagram illustrating the MMGEM (Micro-Mesh GEM) structure. The detector is divided into three regions: Drift region, Transfer region, and Amplification region. The drift region is 100-600 μm thick. The transfer region contains pillars. The amplification region is 128 μm thick. The structure includes a Mylar window, a Test box, a Drift electrode, a Micro-mesh GEM, a Micro-mesh Readout plane, and a Readout plane. A photograph shows the physical MMGEM detector assembly.

← Mylar window
← Test box
Drift electrode
Drift region
100 – 600 μm
pillars
Transfer region
128 μm
Amplification region
Micro-mesh GEM
Micro-mesh Readout plane

Reduces the ion back flow a factor 10 with respect to GEM, MICROMEAS or GEM MICROMEAS hybrid detector

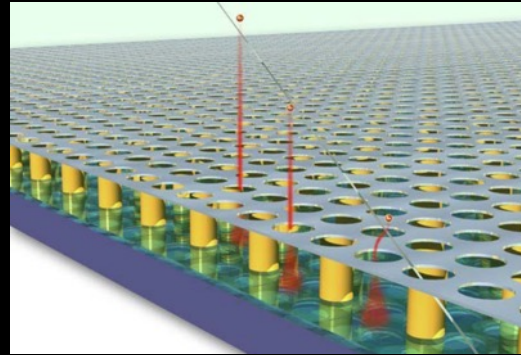
NIMA 1051 (2023) 168134



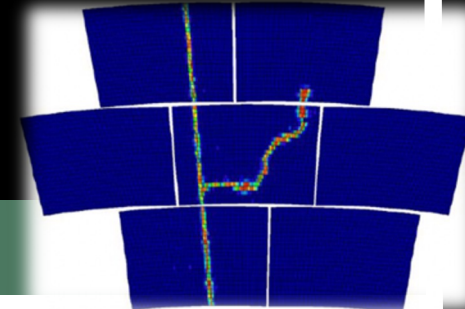
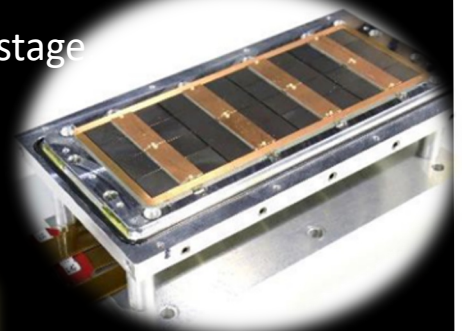
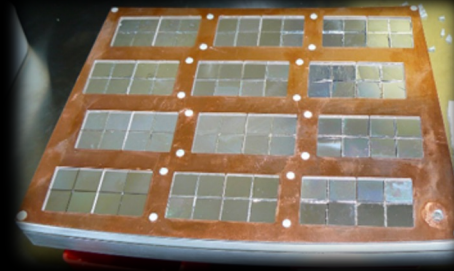
**GEM – MICROMEAS
HYBRID DETECTOR**

GRIDPIX

combines a high density pixelized readout ASIC with a Micromegas gas amplification stage

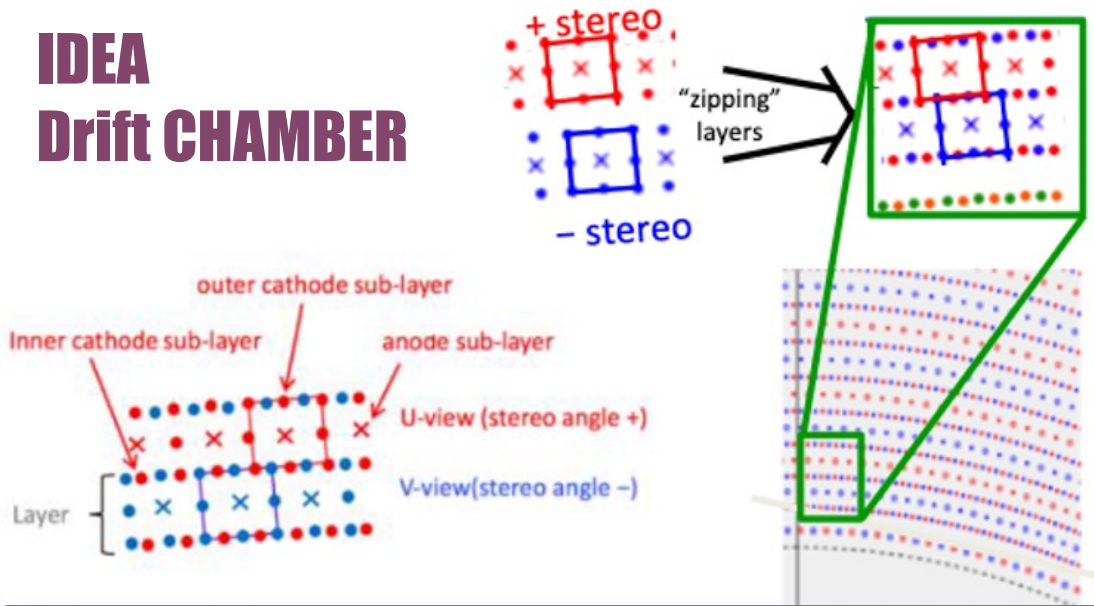


Timepix ASIC with a pixel pitch of $55 \times 55 \mu\text{m}^2$

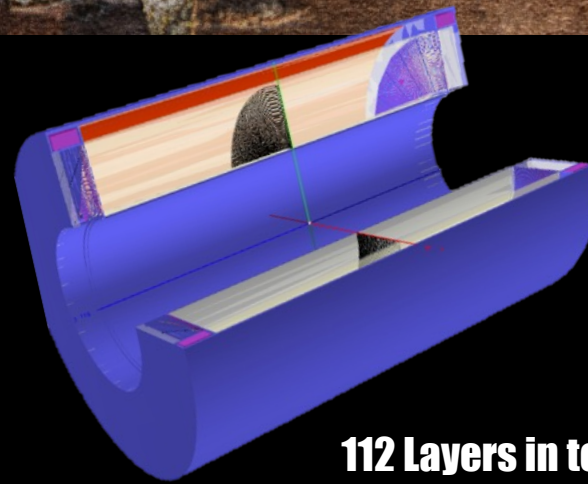


TRACKING - DRIFT CHAMBER

IDEA Drift CHAMBER



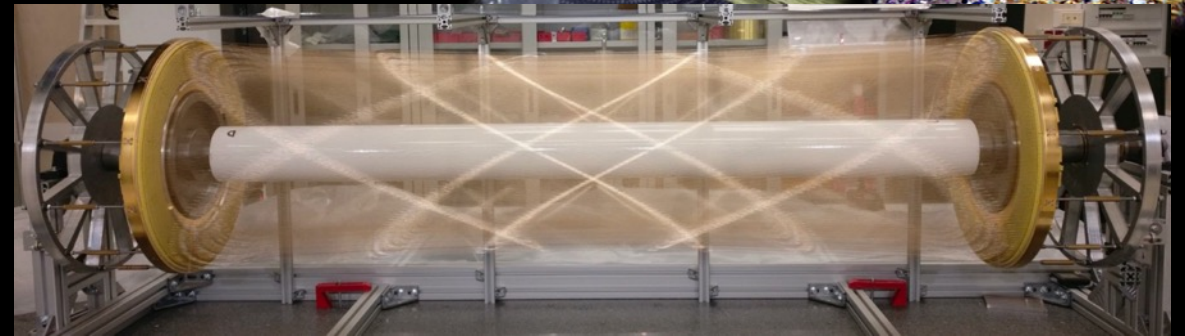
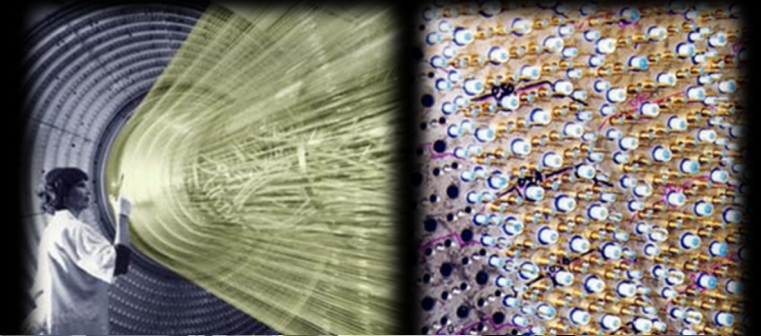
sense wires	20 μm diameter W(Au) \Rightarrow	56448 wires
(thin!!) field wires	40 μm diameter Al(Ag) \Rightarrow	229056 wires
Field between sense and guard wires	50 μm diameter Al(Ag) \Rightarrow	58464 wires
	343968 wires in total	



**112 Layers in total:
14 co-axial super-layers (8 layers each)**

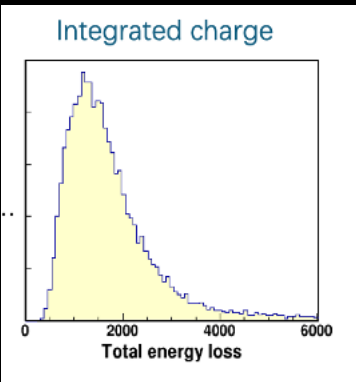
Gas: He:iC₄H₁₀ (90/10)
Inner radius 0.35m
Outer radius 2m
Length 4m
Drift length \sim 1cm
Drift time \sim 150ms
 $\sigma_{xy} < 100\text{mm}$
 $\sigma_z < 1\text{mm}$

Based on the
MEG-II chamber



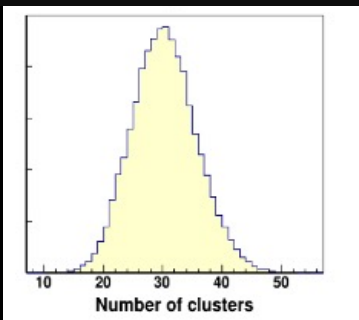
TRACKING - DRIFT CHAMBER: COUNTING CLUSTERS FOR PID

Using dE/dx



Many fluctuations
Driven by the "intrinsic"
Landau fluctuations

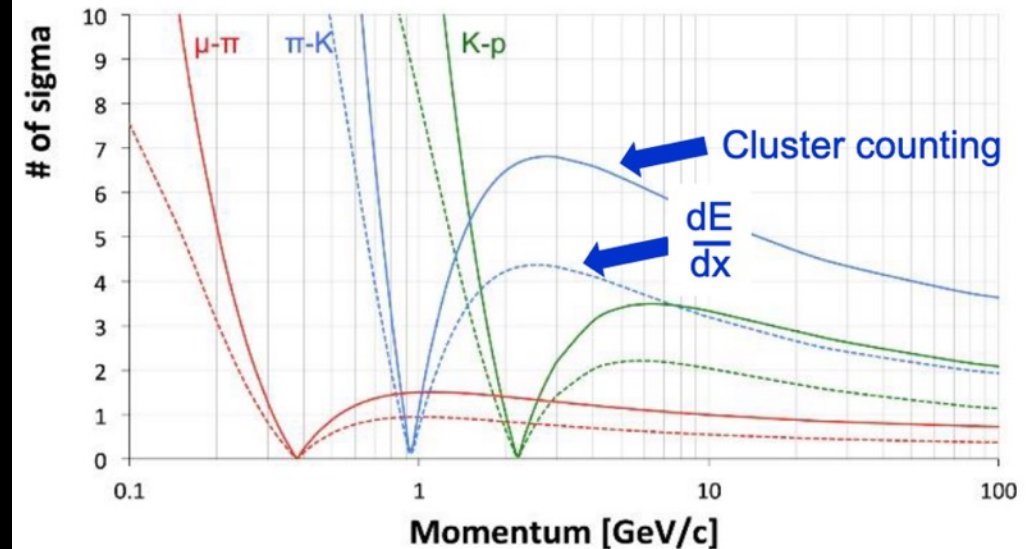
Counting primary clusters



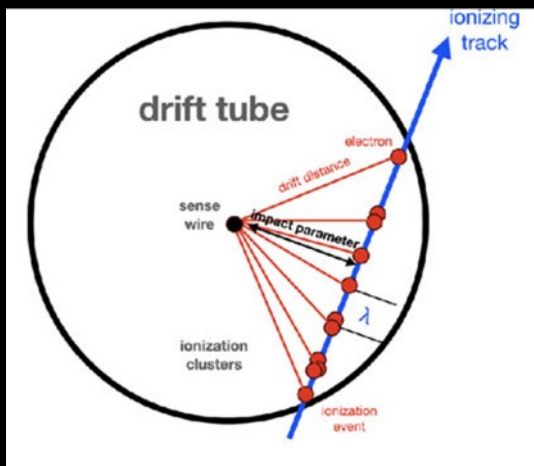
Poisson distribution
Small fluctuations

It is NOT full simulation

Particle Separation (dE/dx vs dN/dx)



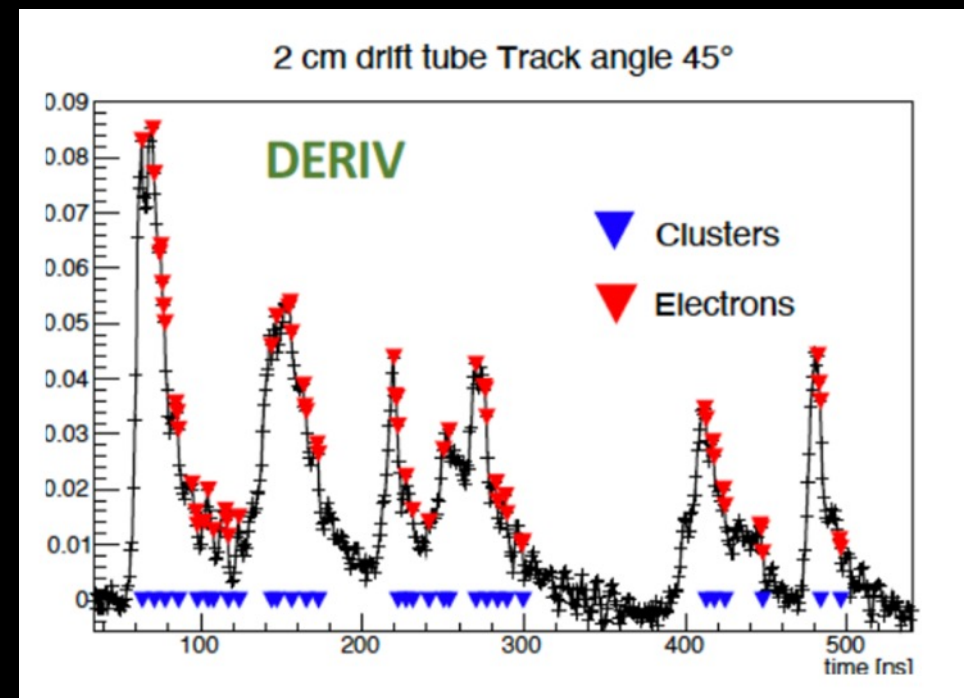
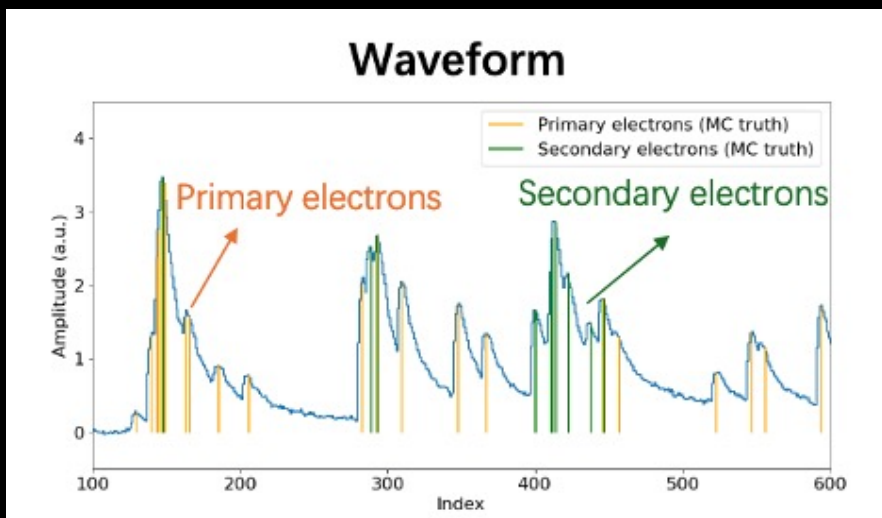
TRACKING - DRIFT CHAMBER: COUNTING CLUSTERS IMPLEMENTATION



Record the arrival time of every cluster generated in every single ionization.
Reconstruct the most likely positions

Several algorithms developed

Test beam data from H8/CERN 2021
Using drift tubes



CALORIMETERS - REQUIREMENTS

Electromagnetic calorimeters:

Resolution:

10%/√E is probably enough for most of the physics studies

But B physics will probably need go down to at least 5%/√E

Very good transversal granularity is required for τ physics

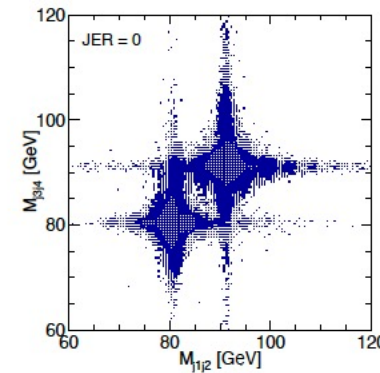
Hadronic calorimeters

Hadronic final states are very relevant players, opening sometimes the access to rare process and helping on increasing statistics

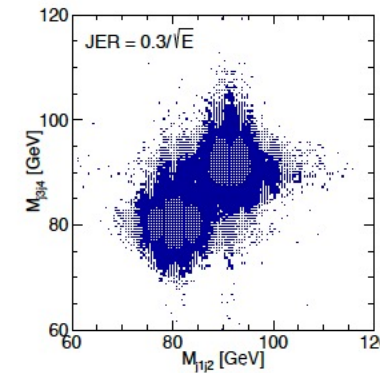
Precision on the jet energy determination plays a very important role

30%/√E is needed, and this represents \sim a factor 2 with respect to the present experiment. The value is driven by the precise separation of Z and W in their hadronic decays and it is comparable to the natural width of Z and W

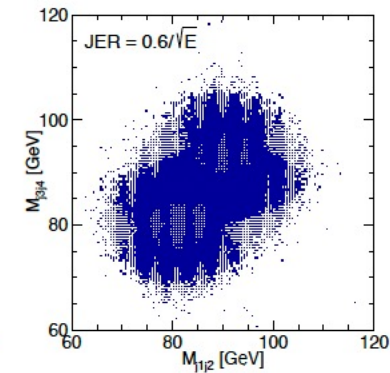
The measurement of jets with the needed precision is the main challenge for the calorimeters



(a)



(b)



(c)

FACING THE CALORIMETER CHALLENGES – JET ENERGY RESOLUTION

Many R&D activities are ongoing, approaching the problems in different ways

Two main different methods to achieve the needed jet resolution for e^+e^- colliders:

- **High granular calorimeters with embedded electronics to apply PFA (Particle Flow Algorithms)**. Developed by the **CALICE Collaboration** along more than 20 years (approach also used for the upgrade of the CMS endcap calorimeter for the HL-LHC). Several technologies as active medium under study: Silicon detectors, scintillators, gaseous detectors

Concepts with PFA fully oriented calorimeters

CEPC Baseline, CLD, CLIC, ILD, SiD, FST,

- **Dual readout Calorimeter**

Concepts with Dual Readout

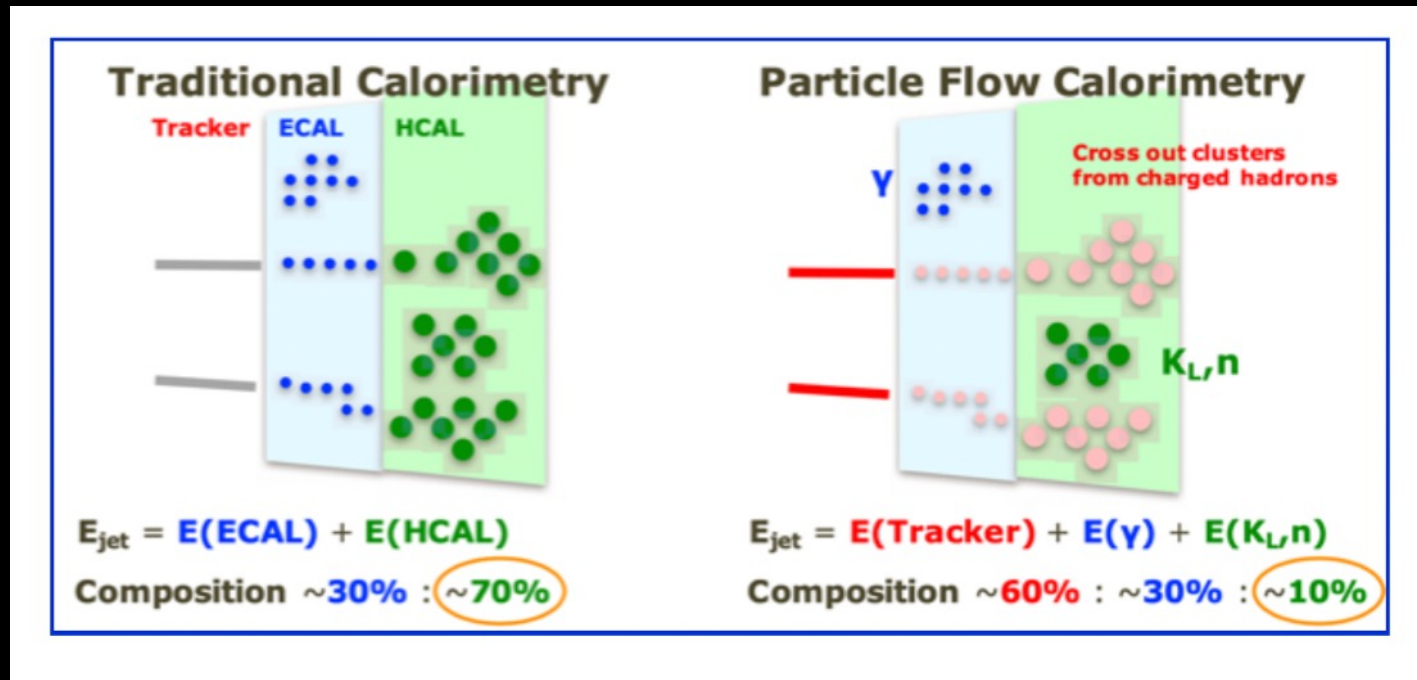
IDEA

FACING THE CALORIMETER CHALLENGES – PFA

Particle Flow Algorithms – PFA

Reconstruct **every single particle** in the event and measure it **only** with the detector providing the best resolution

Average jet composition	PFA reconstruction
60% charged	Measured on the tracker, negligible resolution
30% photons (from π^0 decay)	Measured at ECAL $\sim 10\text{-}20\% \sqrt{E}$
10% neutral hadrons (n, K_L)	Measured at HCAL $\sim 60\text{-}100\% \sqrt{E}$



Very high granularity is needed

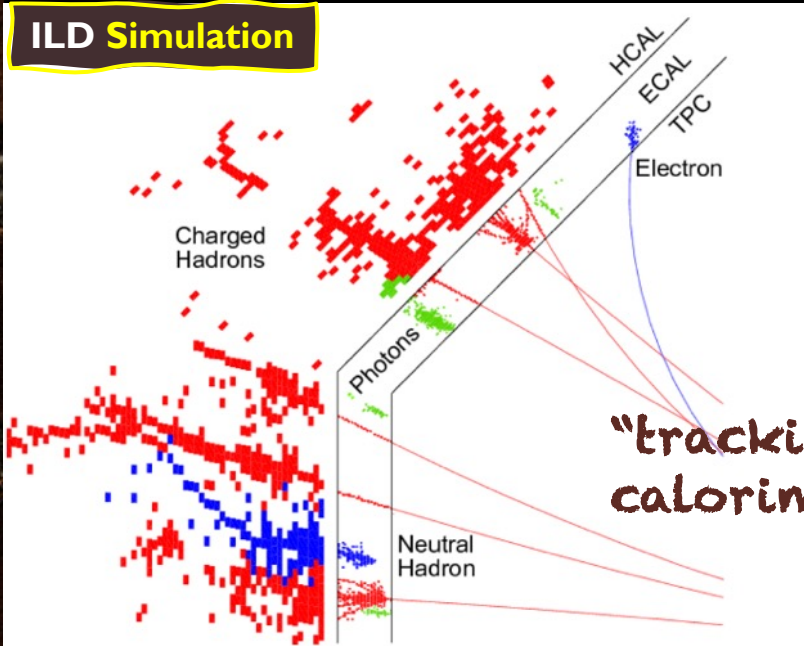
FACING THE CALORIMETER CHALLENGES – PFA

Particle Flow Algorithms – PFA

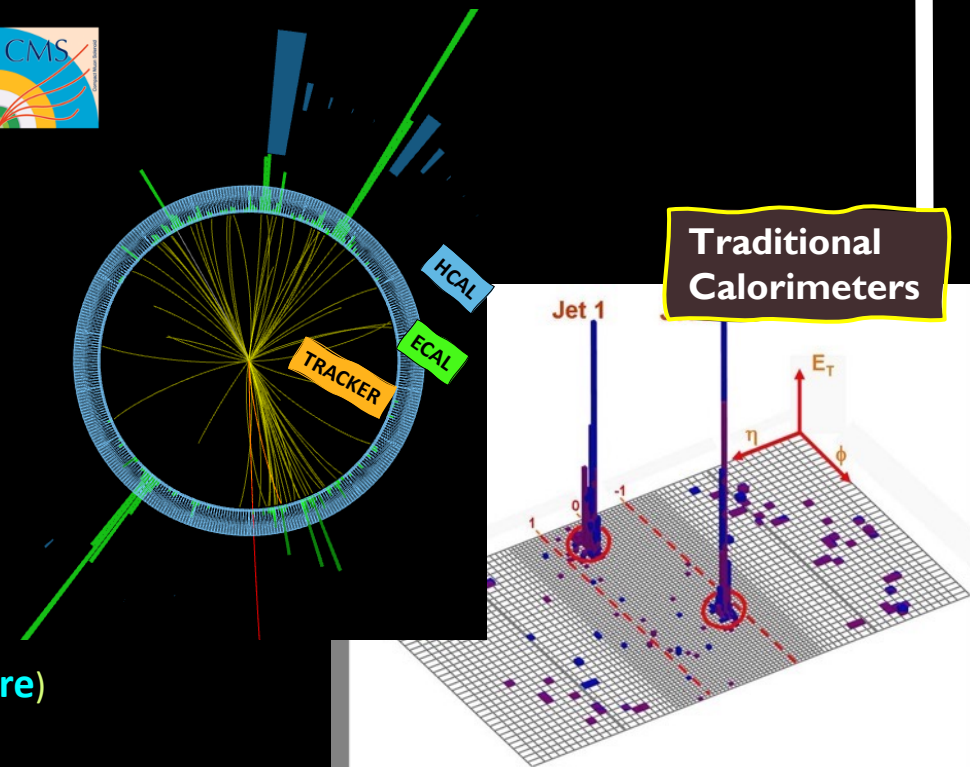
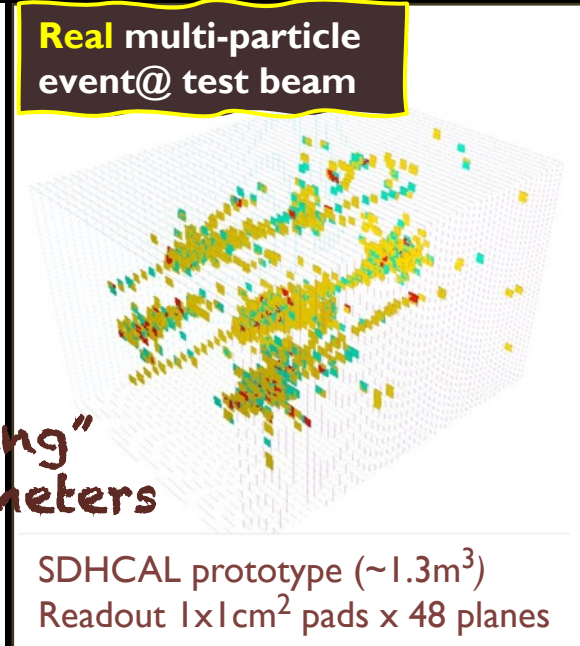
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ILD Simulation



Real multi-particle event@ test beam



Main resolution challenge: **Confusion**

Bad assignment of energy between particles (**software**)
+ overlap in the same readout channel (**granularity**)

FACING THE CALORIMETER CHALLENGES – DUAL READOUT CONCEPT

Remember that in a **hadronic calorimeter** there are two components

$$\text{Signal} = S_{em} + S_{had} = e f_{em} E + h f_{had} E$$

$$f_{had} = 1 - f_{em}$$

$$\frac{e}{h} = 1$$

Compensating
Calorimeter

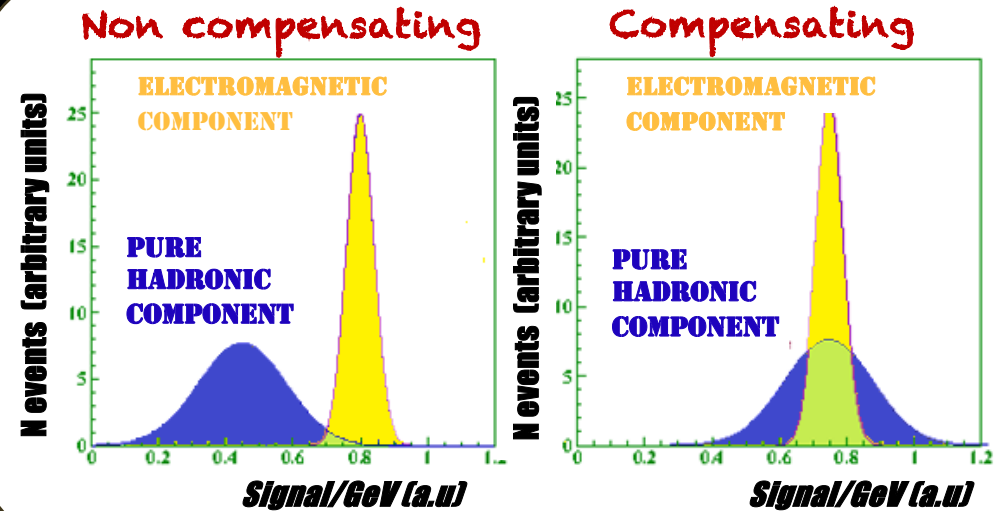
If it could be possible to distinguish in the calorimeter the electromagnetic fraction, compensation is not needed

This can be achieved by using two different materials for producing different light type:

1. Cherenkov light, produced by relativistic particles dominated by **electromagnetic components** (80% of the hadronic component is not relativistic)
2. Scintillator light

It can be implemented for example using fibers embedded in the calorimeter absorber

A combination of dual-readout + PFA could also be envisaged



FACING THE CALORIMETER CHALLENGES – POWER CONSUMPTION

FACTS

- The huge number of channels, two orders of magnitude higher with respect actual calorimeters, implies a large power consumption.
- The need of compact devices with electronics embedded on the detector planes and large power consumption increase the heat.

Solutions

At e^+e^- linear colliders

Use of power pulsing electronics profiting from the duty cycle (1%)

ILC provides bunches with a rate of 3 – 5MHz for a period of 1ms, followed by an inactive gap of 199ms.

Switch off / stand-by the the front-end electronics during the gaps in between the bunch trains

Already implemented and successfully tested at some CALICE prototypes

At Circular colliders

Continuous rate of collisions

Active cooling could be needed if the electronics power consumption cannot be reduce

Challenging to maintain compactness and uniformity
(important for high performance)

TOWARDS 5D CALORIMETERS?

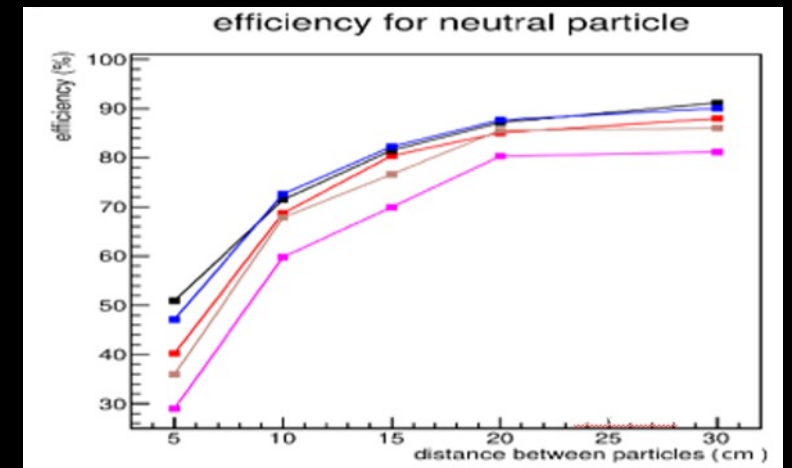
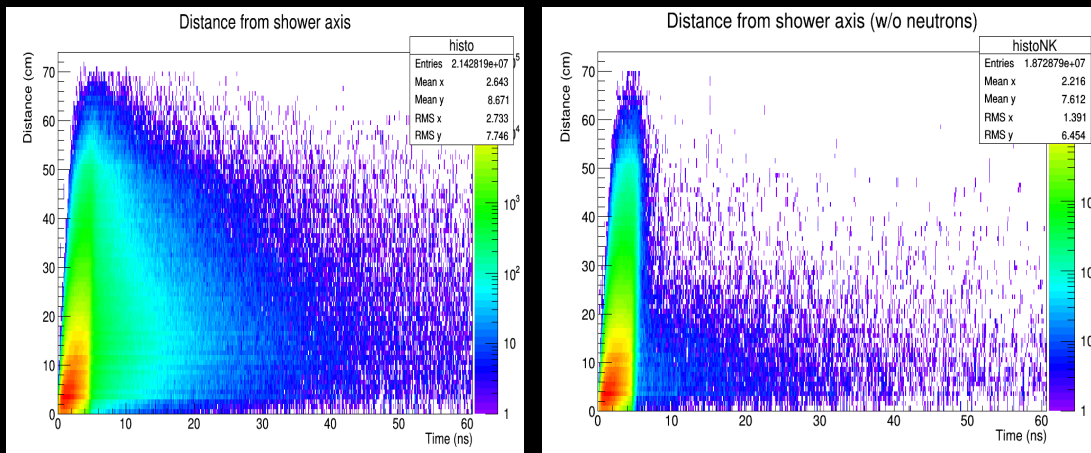
Precise time information was not a requirement for calorimeters, but it could be very useful for the future.

Timing in calorimeters could mitigate backgrounds/pileup, be used for ToF measurements, or eventually recognize signatures for neutral long live particles.

But it can be also useful at the calorimeter reconstruction level when having a highly segmented calorimeter which reconstruct individual hits and gives an image of the shower.

- Can be used for **distinguish hits from different showers**, improving the efficiency and resolution for reconstruction close by particles
- Can be used for **improving the single particle resolution** by taking into account the timing of the different particles in the shower

10 GeV neutral from 30 GeV charged particle

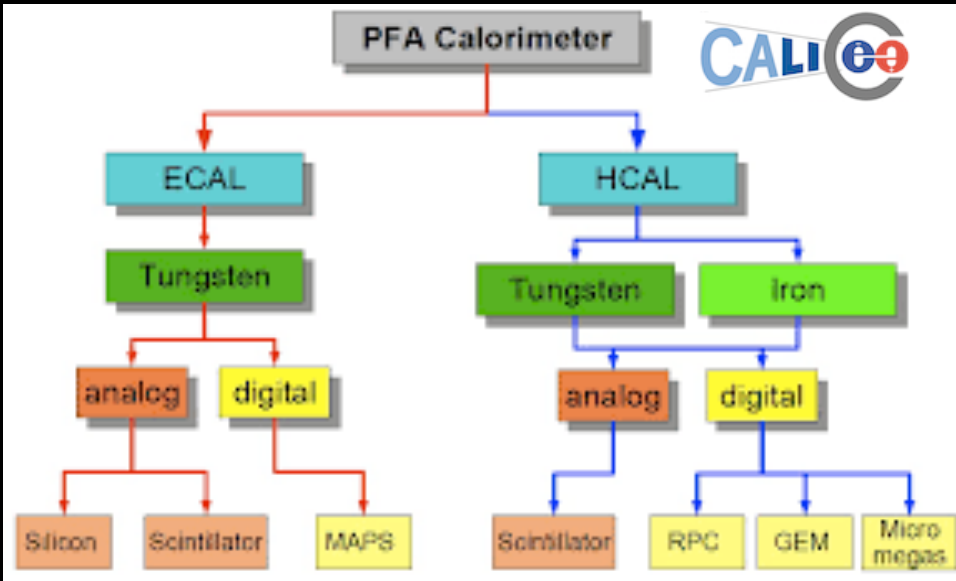


**A lot of developments on going on
calorimeters, detector concepts still
open to different options or different
implementations**

CANNOT BE FULLY REVIEW IN THIS TALK

JUST AN OVERVIEW

HIGHLY SEGMENTED IMAGING CALORIMETERS OPTIMIZED FOR PFA



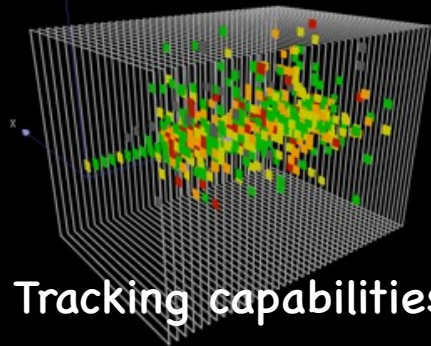
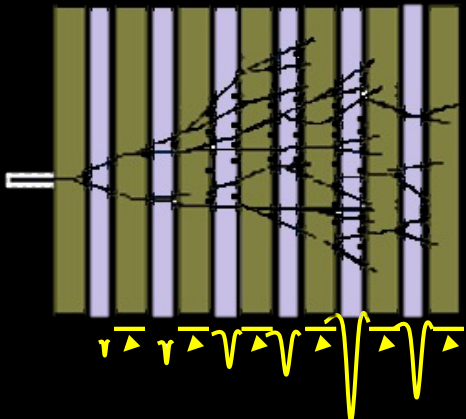
Tungsten absorber for ECAL.

$\lambda_I/X_0 \sim 9 \rightarrow$ excellent photon–hadron separation.
Important for PFA

$X_0 \sim 3.5$ mm (vs 1.76 cm in iron) \rightarrow Compact

Tungsten has been considered as HCAL absorber only for CLIC
Compact detector for very high energetic particles
(problem: very expensive)

Sandwich calorimeters



Tracking capabilities

Run: 50225 Event: 2829 Date: 09.05.2018 Time: 14:27:33.000000000

SOME GENERAL CONCEPTS ON CALICE CALORIMETERS

CALICE calorimeters are oriented to be used with PFA. → High granularity is a must

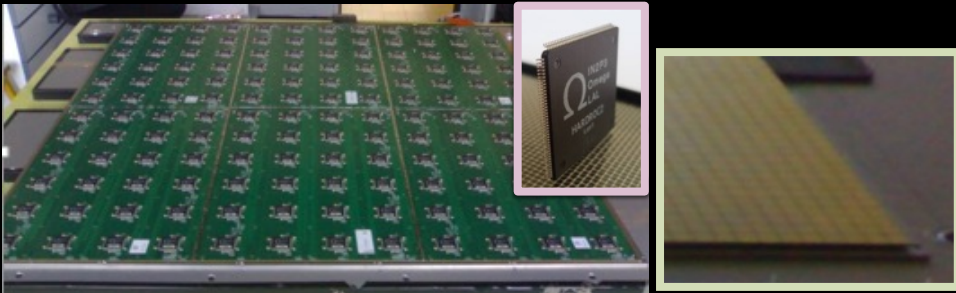
- Large segmentation, longitudinal and transversal

What large means?

The longitudinal segmentation is 1 layer sampling every
 $\sim 0.1 X_0$ for ECAL and $\sim 0.1 \lambda_1$ for HCAL

The transversal segmentation goes, from $25 \mu\text{m} \times 100 \mu\text{m}$
Pixels in **DMAPS ECAL** till $\sim 3 \times 3 \text{cm}^2$ pads in **AHCAL**

- FE electronics is embedded into the layer structure (at least on final design, intermediate prototypes could be not fully optimized)



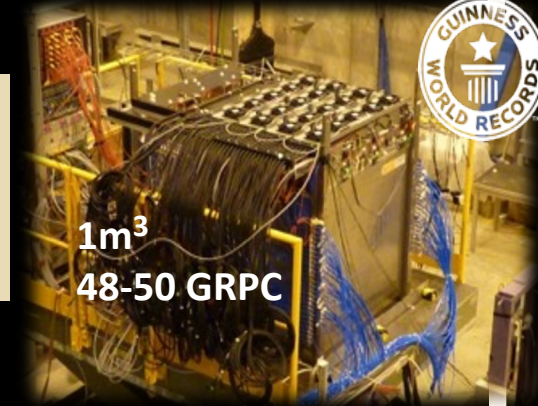
PCB boards

Bottom has the pads/strips
Top has ASIC chips

The number of channels is orders of magnitude bigger than the ones in the present experiments

SDHCAL $1 \times 1 \text{cm}^2$ pads

500K Channels



1m^3

48-50 GRPC

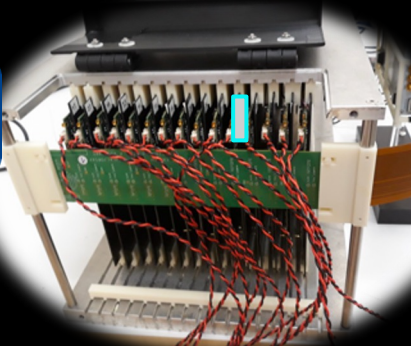
More channels in this prototype than in the LHC calorimeters all together

- Final electronics implements power pulsing mode, but now looking also to other options in view of circular colliders
- Dead spaces must be minimize, this includes tiny space between each detector and the absorber → High precision mechanics needed

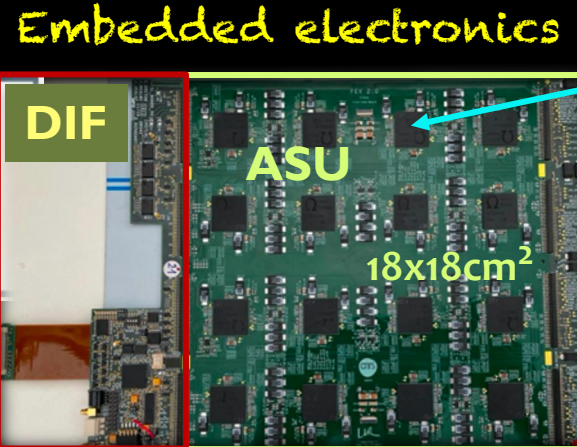
SILICON BASED SANDWICH CALORIMETERS

SI-W ECAL – PROTOTYPES UNDER DEVELOPMENT

Mature technology developed by CALICE since years
Adapted for the CMS HGCAL upgrade calorimeter



- SiW-ECAL**
- 15 layers 18x18 cm²
 - 0.5x0.5 cm² Si cells
 - 2.8+5.6 mm W (21 X₀)
 - 100 kg, 0.4x0.4x80 cm³
 - 15k channels



DIF

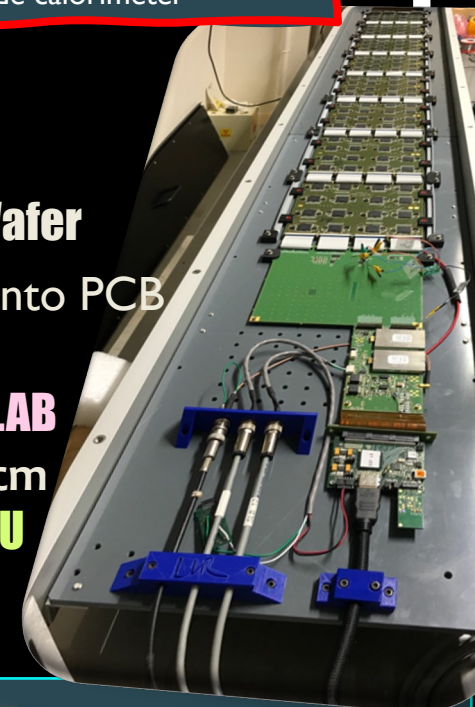
ASU
18x18cm²

ASIC SKIROC2

ASU = ASIC+PCB+SiWafer

Silicon sensors glue onto PCB

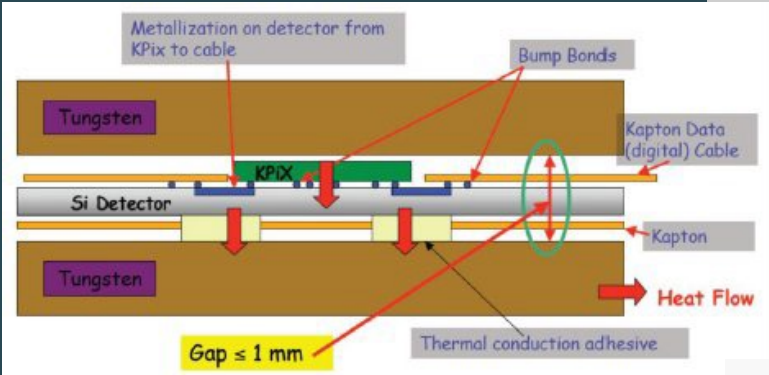
LONG SLAB
~150cm
7 ASU



FUTURE R&D STEPS

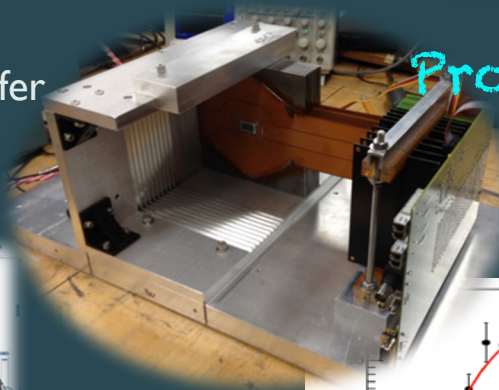
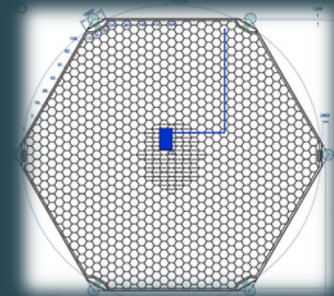
- Moving from power pulsing to continuous redout for circular colliders. Power consumption, cooling
- Addition of timing (dedicated layers or full device)

DIF = Detector InterFace: SL Board



Hexagonal sensor Wafers

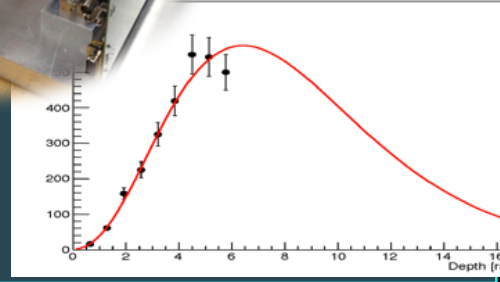
- 1 **KPIX ASIC** (1024 ch) per Wafer
- Optimized for ILC (power pulsing, multihit)



Prototype

9 Silicon layers
~6X₀

ASIC and cable bonded to sensor
Tungsten plates thermal bridge to edge cooling

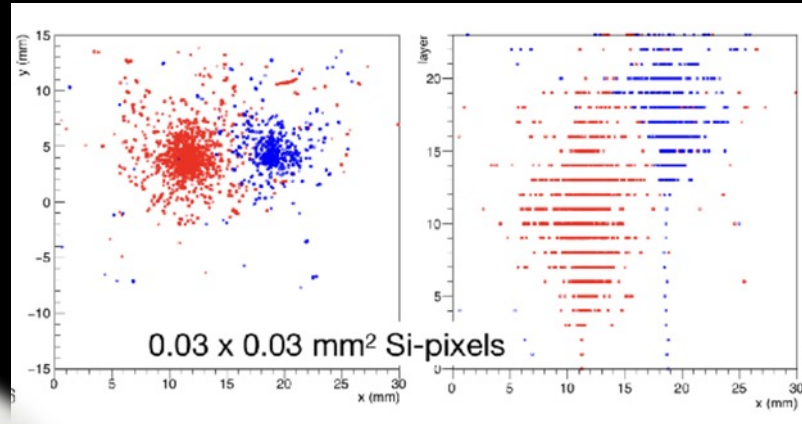
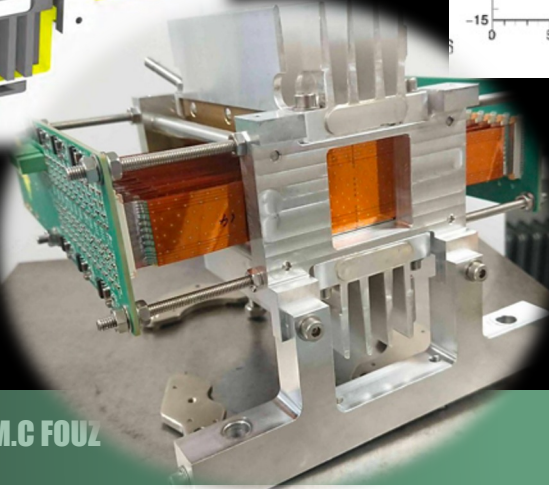
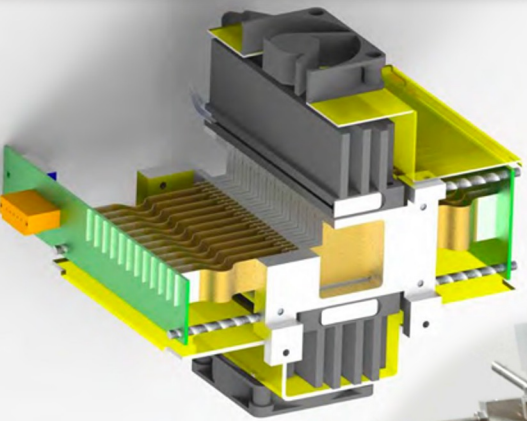


SILICON BASED SANDWICH CALORIMETERS

DMAPS ECAL

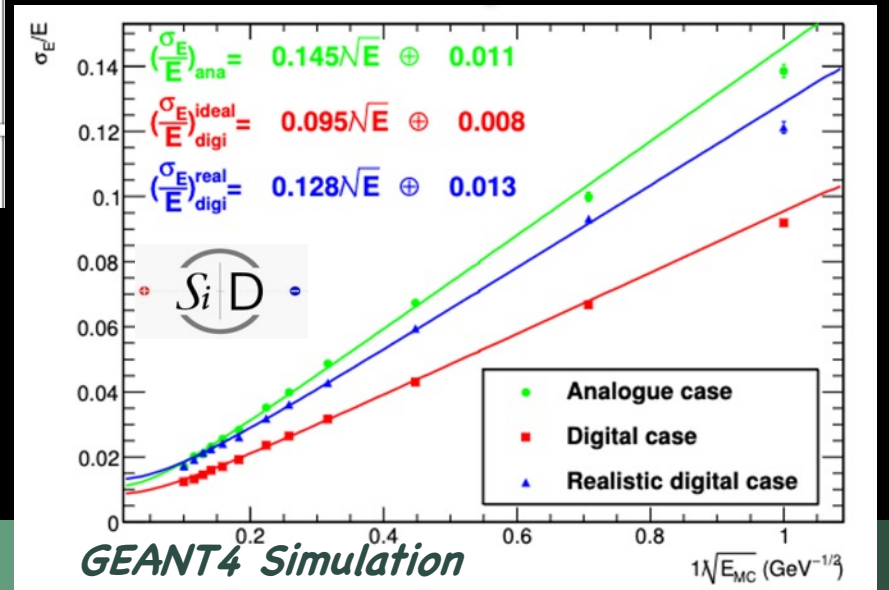
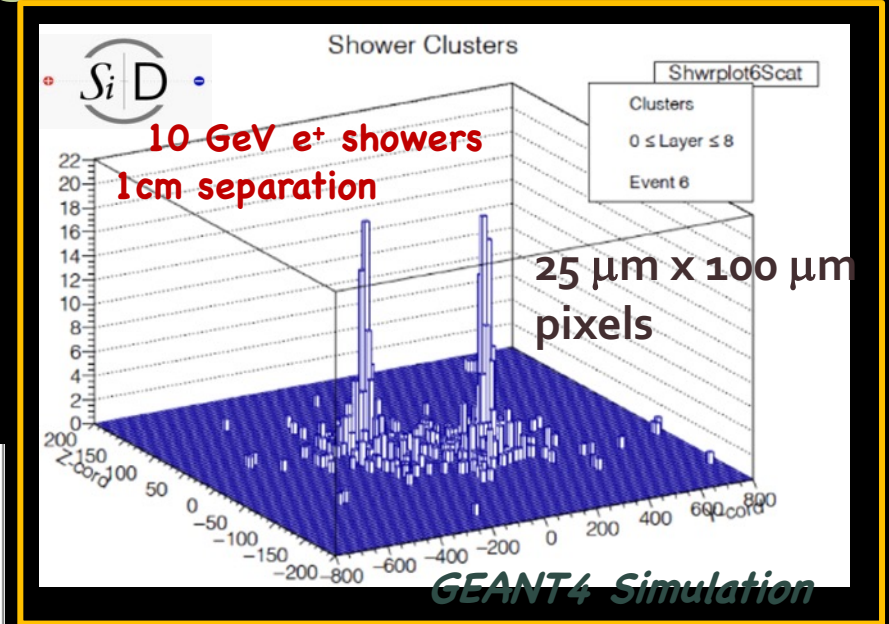
Monolithic Active Pixel Sensors (MAPS) as sensor with Digital Readout
 Si diodes and readout combined in the pixel and build with standard CMOS process

- Bump-bonding not needed (easier, cheaper)
- Fine granularity of pixels (better separation of showers)



EPICAL-2 prototype

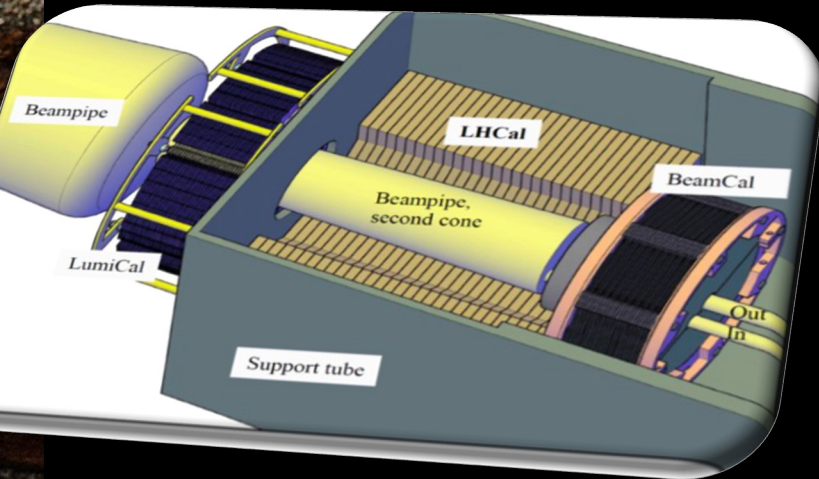
28 layers
 ALPIDE CMOS sensors.
 Active cross section 3x3cm²



SILICON BASED SANDWICH CALORIMETERS FOR FORWARD CALORIMETERS

LC FORWARD CALORIMETERS

Similar still to be developed for FCCee



REQUIREMENTS

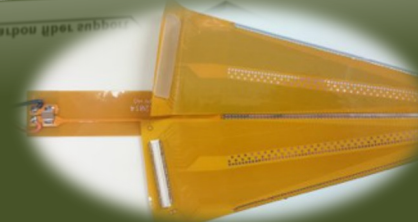
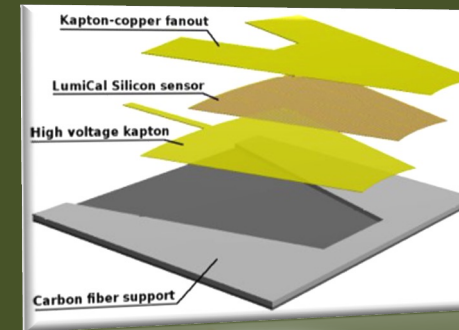
- Finely segmented and compact (Small Molière radius)
- Mechanical precision (polar angle measurement)
- Fast readout
- Radiation hard (BeamCal)

LumiCal: Precise luminosity measurement (Bhabha) (10^{-3}) at 500 GeV.
SiW ECAL

BeamCal: Instantaneous luminosity measurement, beam diagnostics
very high radiation load (up to 1MGy/ year)
W + radiation hard sensors (GaAs, CVD Diamon, Sapphire)

LHCAL: Extends the calorimeter measurements to small polar angles
SiW or Si+iron

LumiCAL

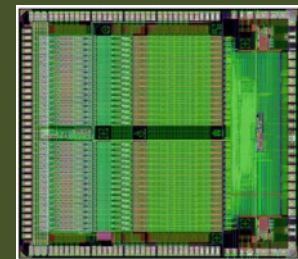


15 Detector planes
FLAME ASIC

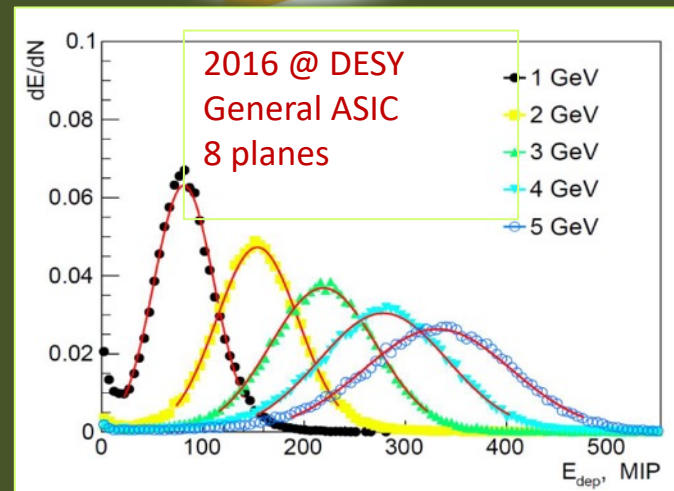


FLAME

FcaL Asic for
Multiplane
readout

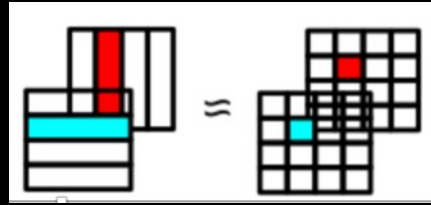


3.7 x 4.3 mm²



OPTICAL BASED SANDWICH CALORIMETERS: SCW-ECAL

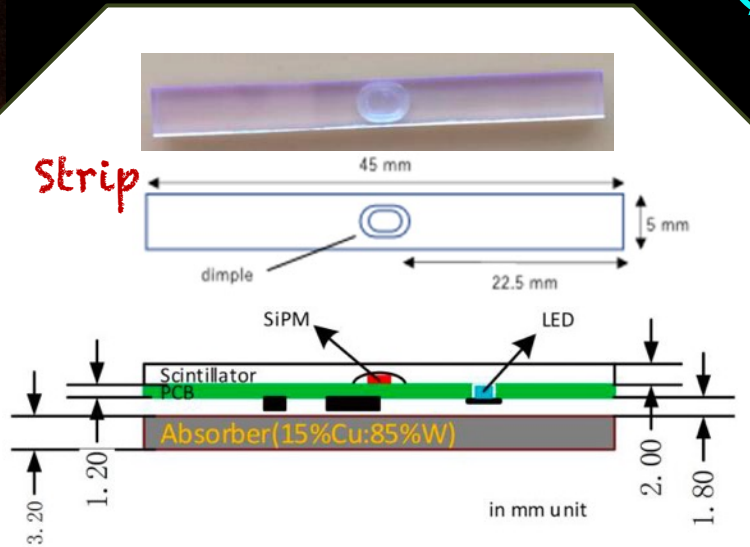
Sensor: Plastic scintillator
Readout: Strips (5 x 45 mm²)
- SiPM



(5x45 mm²) → (5x5 mm²)

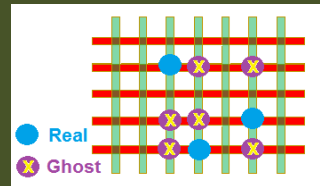
Less readout channels than SiW-ECAL

Possibility of introducing dedicated timing layer(s)



Cheaper 🍌
(plastic and electronics)

Ghosts 🍇

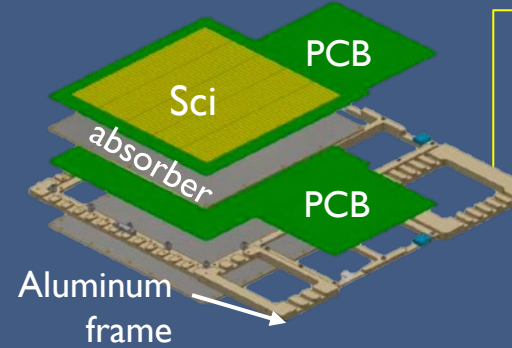


Should be eliminated by double SiPM readout

90mm (dimples at both ends)

43

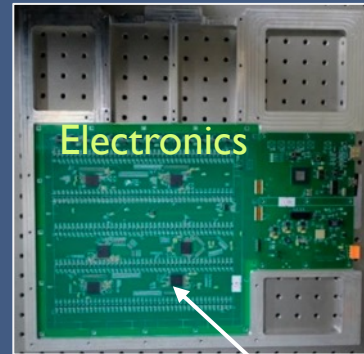
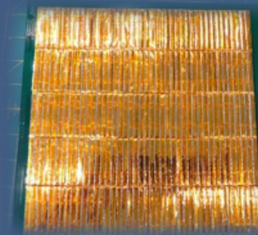
Prototype



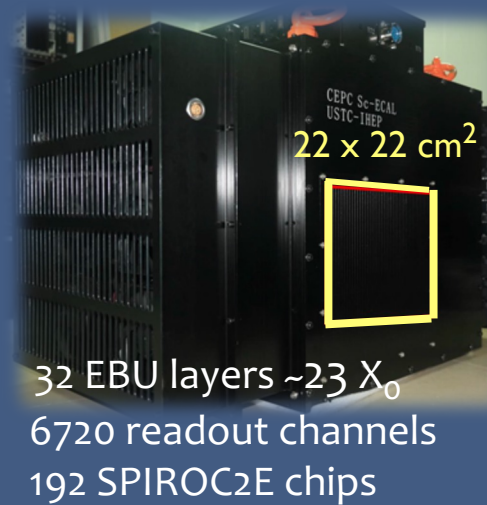
ECAL Basic Unit (EBU)

- Scintillator strips + Hamamatsu SiPMs + SPIROC2E chips
- Tungsten-copper alloy (85:15)

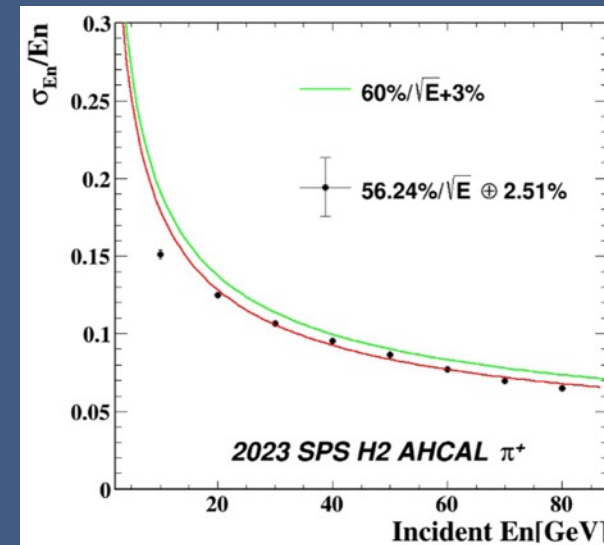
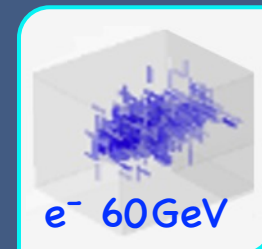
Scintillator plane
42 x 15 strips



SPIROC2E



32 EBU layers ~23 X₀
6720 readout channels
192 SPIROC2E chips

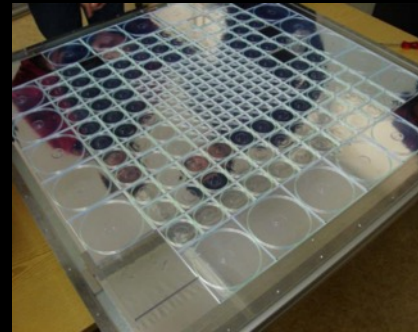


OPTICAL BASED SANDWICH CALORIMETERS: AHCAL

Mature technology developed by CALICE since years
Also adapted for the CMS HGCAL upgrade calorimeter

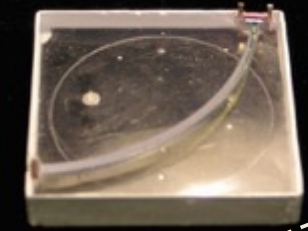
Absorber: *Stainless steel (*)*
Sensor: *Plastic scintillator*
Readout: *Tiles (3 x 3 cm²)*
- SiPM
() Tungsten also tested for CLIC*

Many technical developments after the first prototype used as a probe of concept

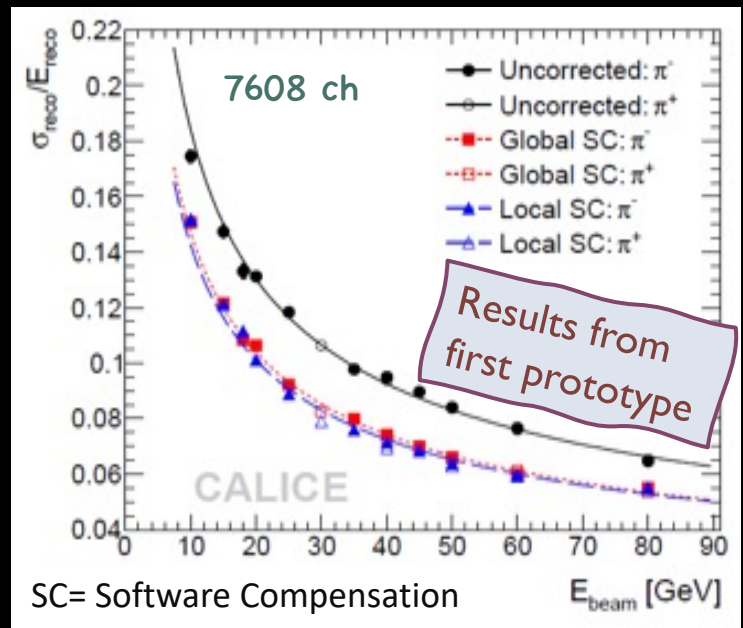


First prototype

1 plane.
Diferent sizes:
3x3cm² (30x30 cm² core)
6x6cm² 12x12 cm² (external)

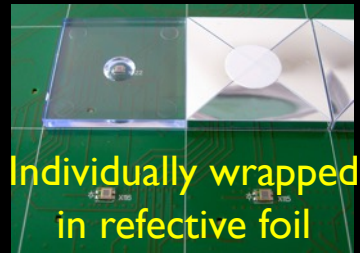


Old Tile design



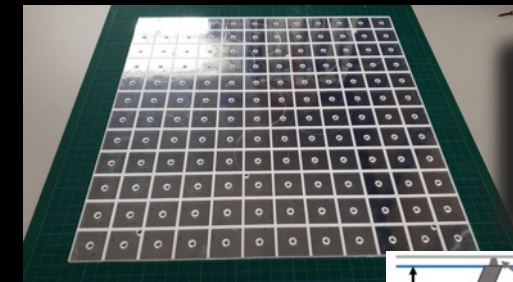
New Developments

Single Tile design



Individually wrapped in reflective foil

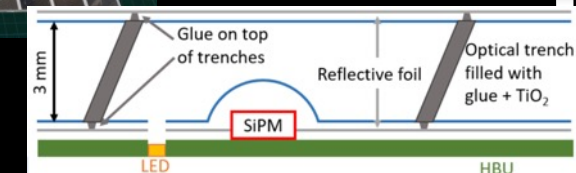
Glued one by one
Light Tightness 👍
Dead areas between tiles 🙄



Megatile design
Large scintillator plate with optically separated trenches filled with reflective TiO₂

Plate wrapped in reflective foil

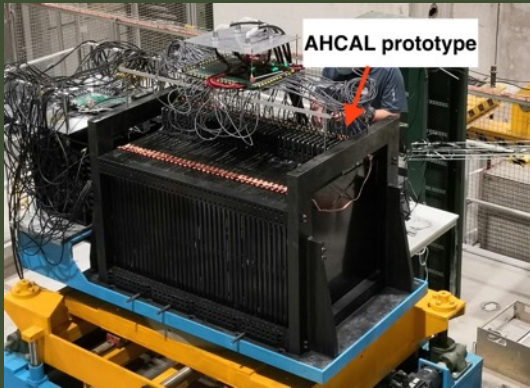
Easier assembly and no dead areas 👍
Not fully light tight 🙄



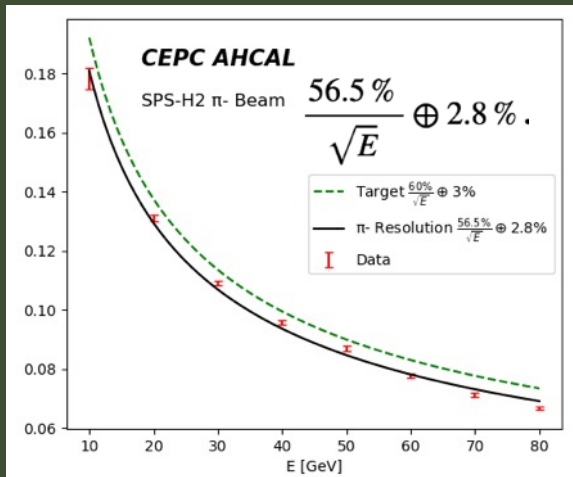
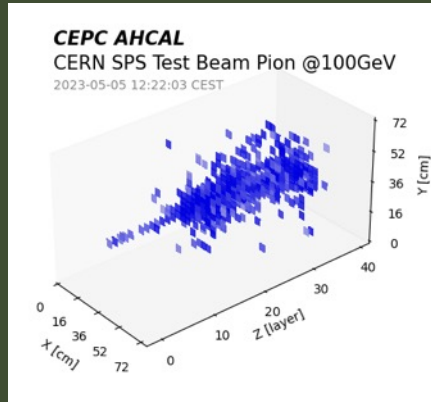
OPTICAL BASED SANDWICH CALORIMETERS: AHCAL PROTOTYPES UNDER DEVELOPMENTS/TESTS

Two similar prototypes built. Several beam tests and data under analysis
Both uses power pulsing electronics

Prototype for CEPC



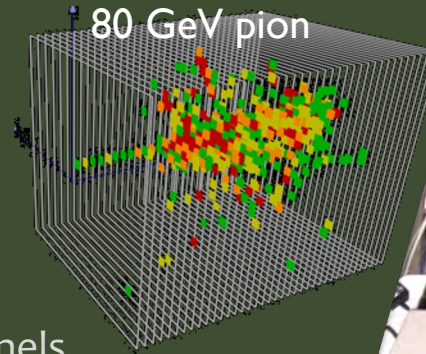
Tiles $4 \times 4 \times 0.3 \text{ cm}^3$
40 layers $0.72 \times 0.72 \text{ m}^2$
~13.000 channels



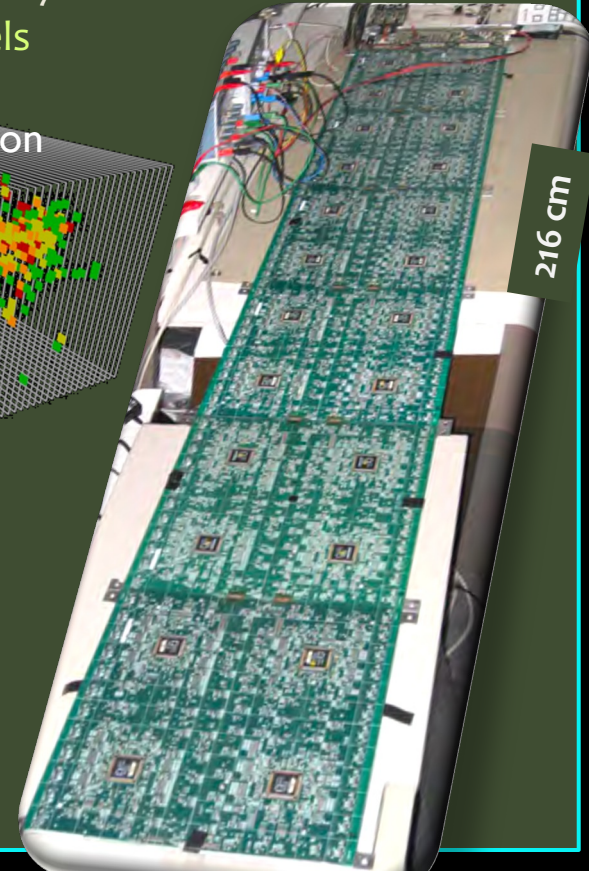
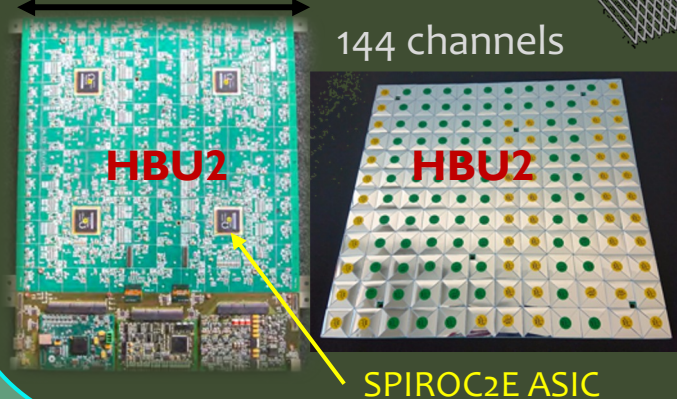
Prototype for ILC

Tiles $3 \times 3 \times 0.3 \text{ cm}^3$
38 layers $0.72 \times 0.72 \text{ m}^2$
~22.000 channels

Full extension
1 slab = 6 HBU2



HBU: HCAL Base Unit
36 cm



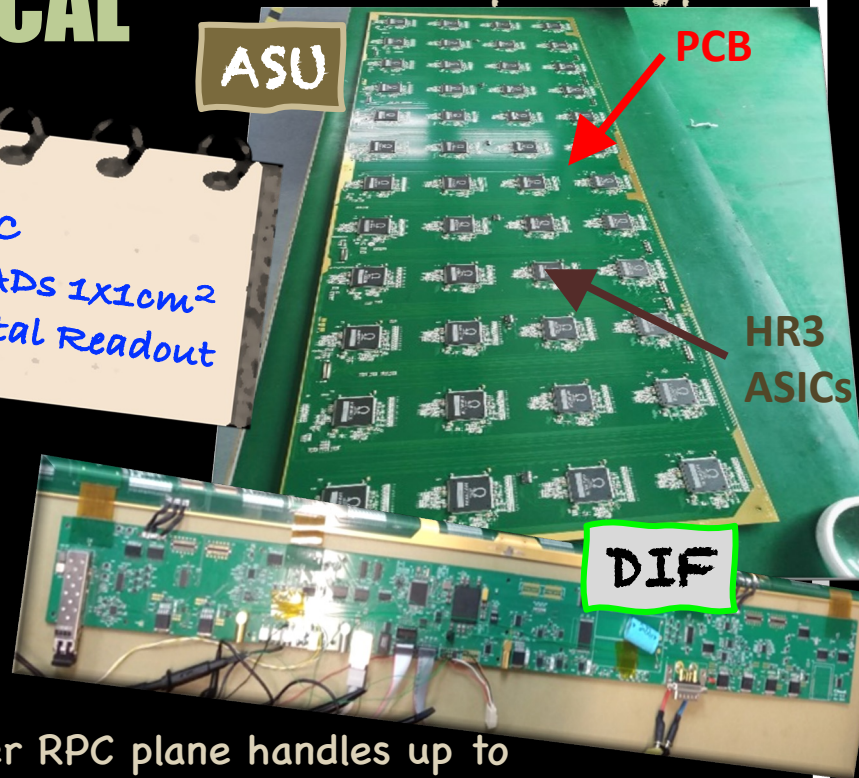
GAS BASED SANDWICH CALORIMETERS: SDHCAL



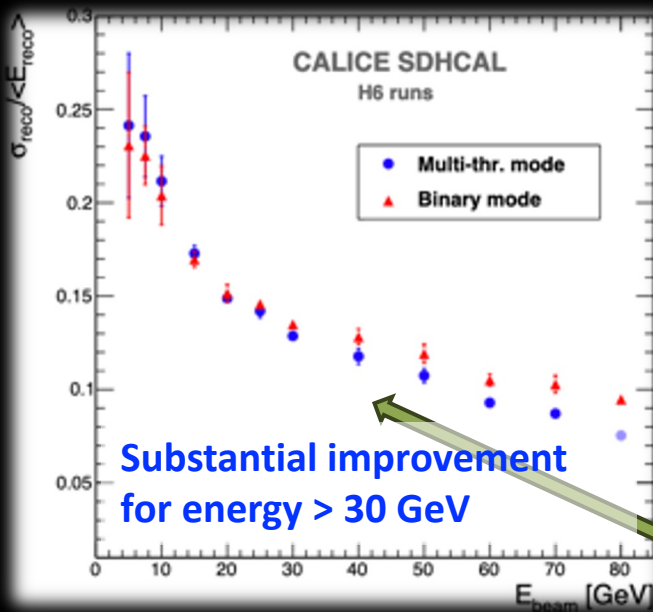
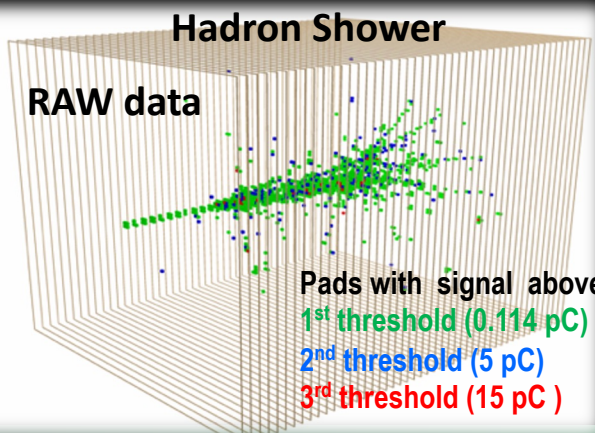
- 48 layers ($-6\lambda_I$)
- 1 cm x 1 cm granularity
3-threshold, 500000 channels
Semi-digital readout
- Power-Pulsed
- Triggerless DAQ system
- Self-supporting mechanical structure ($<500 \mu\text{m}$ deformation)

Sensor: RPC
Readout: PADS 1x1cm²
Semi-digital Readout

Large prototypes



SDHCAL ~1.3m³ prototype
At Test Beam @ CERN



1 DIF per RPC plane handles up to 432 HR3 chips. (1x3m²) chamber

Advantage of semi-digital vs digital
→ Multi-threshold improves resolution

Technology under development by CALICE since more than 10 years

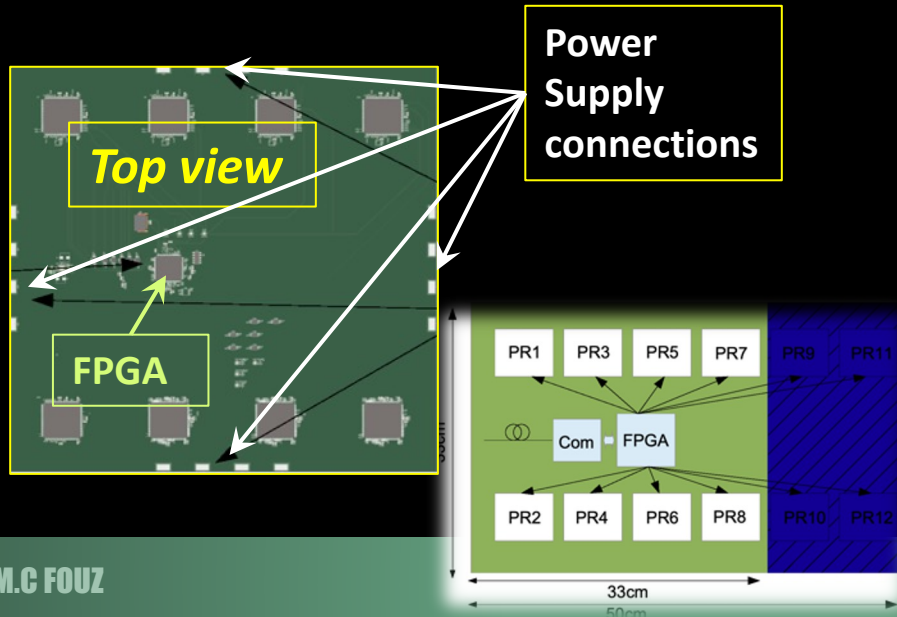
GAS BASED SANDWICH CALORIMETERS

TSDHCAL – TOWARDS A 5D-SDHCAL CALORIMETER

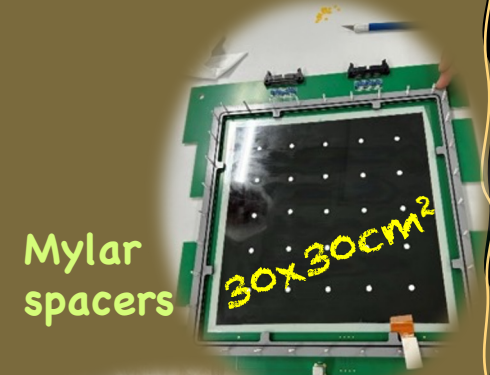
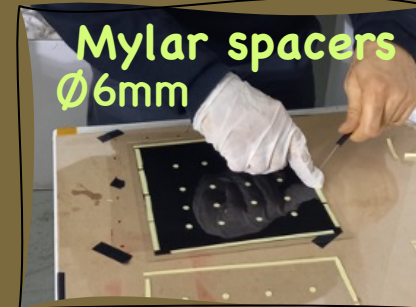
Goal: Time resolution better than 100 ps/mip

- RPC are replaced by **MultiGap RPC -MRPC** (faster)
- Semi-digital electronics (HARDROC) is replaced by low-time jitter **PETIROC** (> 20 ps @ $Q > 300$ fC)

New Boards designed



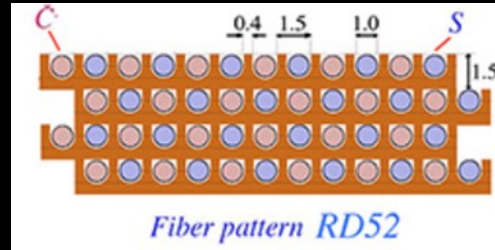
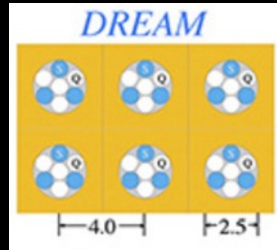
Several MPRC developments



DOUBLE READOUT FIBER CALORIMETER

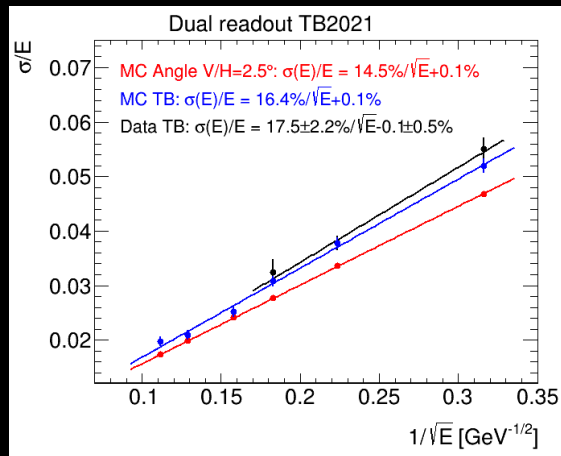
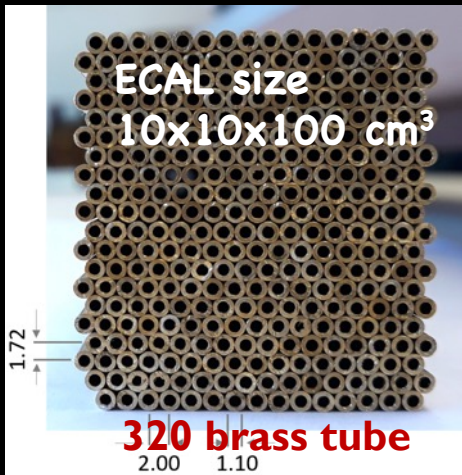
Geometry based on metal capillaries acting as absorber with inserted fibers

Absorber: brass or steel
 Sensor: Scintillator + cherenkov
 Fibers
 Readout: SiPM/MCP-PMT
 Dual readout

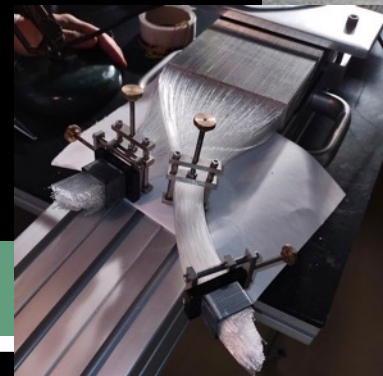
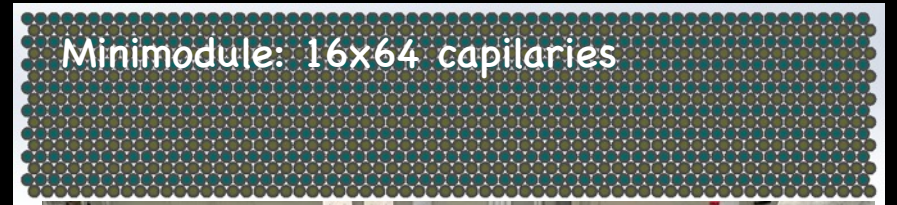


Readout with a SiPM or PMT

Several prototypes under development



HCAL size 65x65x250 cm³. → 80 minimodules.

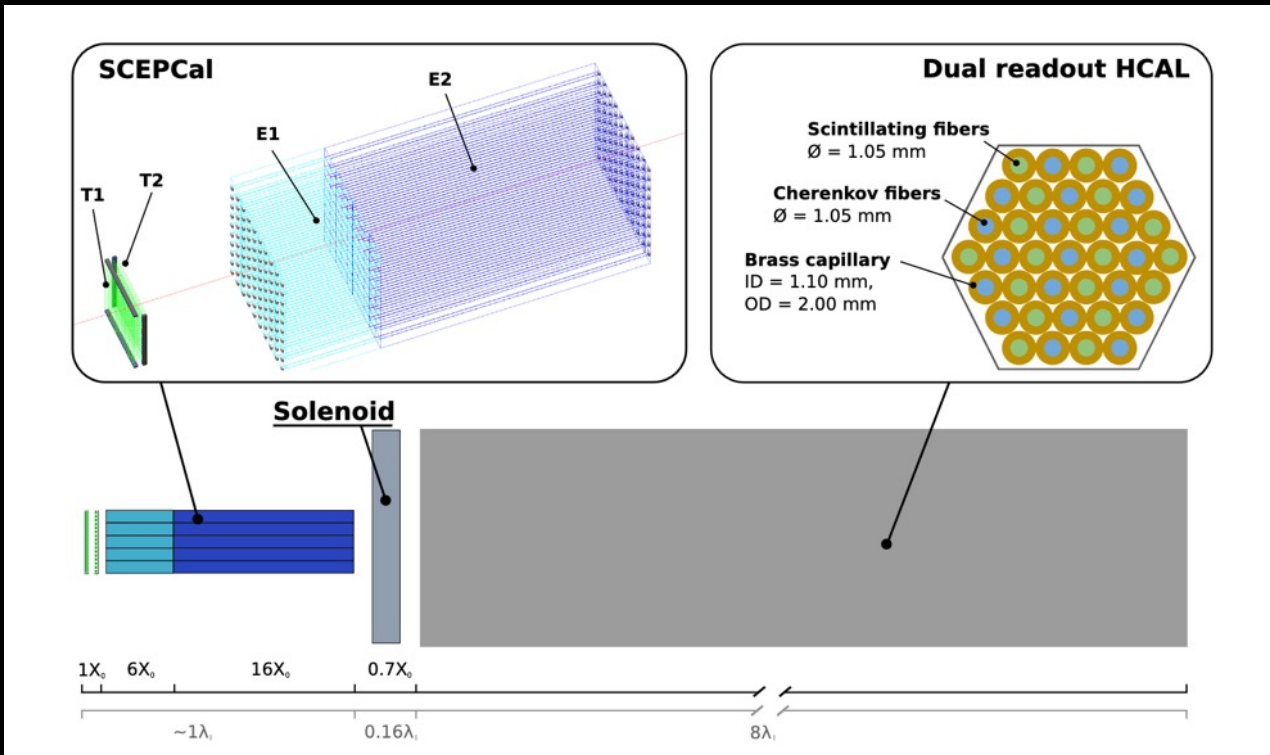


DOUBLE READOUT CRYSTAL CALORIMETER: SCEPCAL

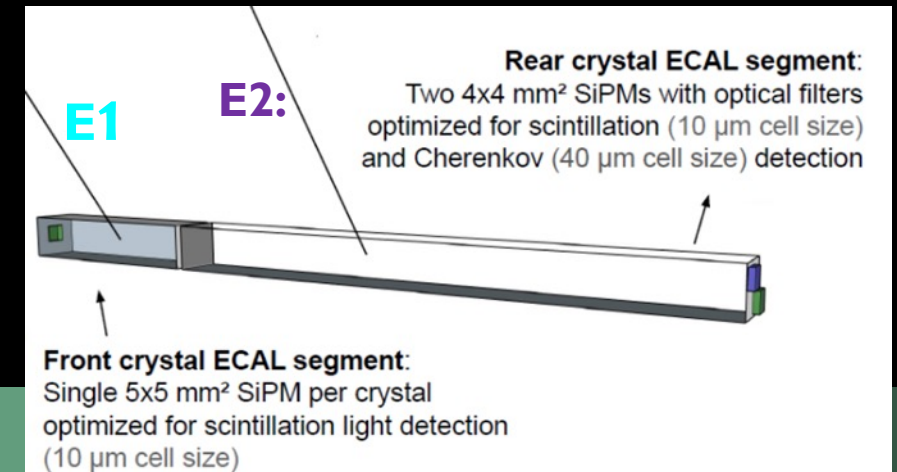
SCEPCAL: Segmented Electromagnetic Precision CALorimeter

FT1, T2 Fast and bright Scintillator
(e.g LYSON:Ce Crystals)
MIP tagging 20 ps

E1, E2: Dense crystal with dual-readout capabilities (PBWO4, BFP, BSO)
Precise measurement EM showers



Scintillator and Cherenkov from the same active medium, disentangle using optical filters



NOBLE LIQUID CALORIMETER

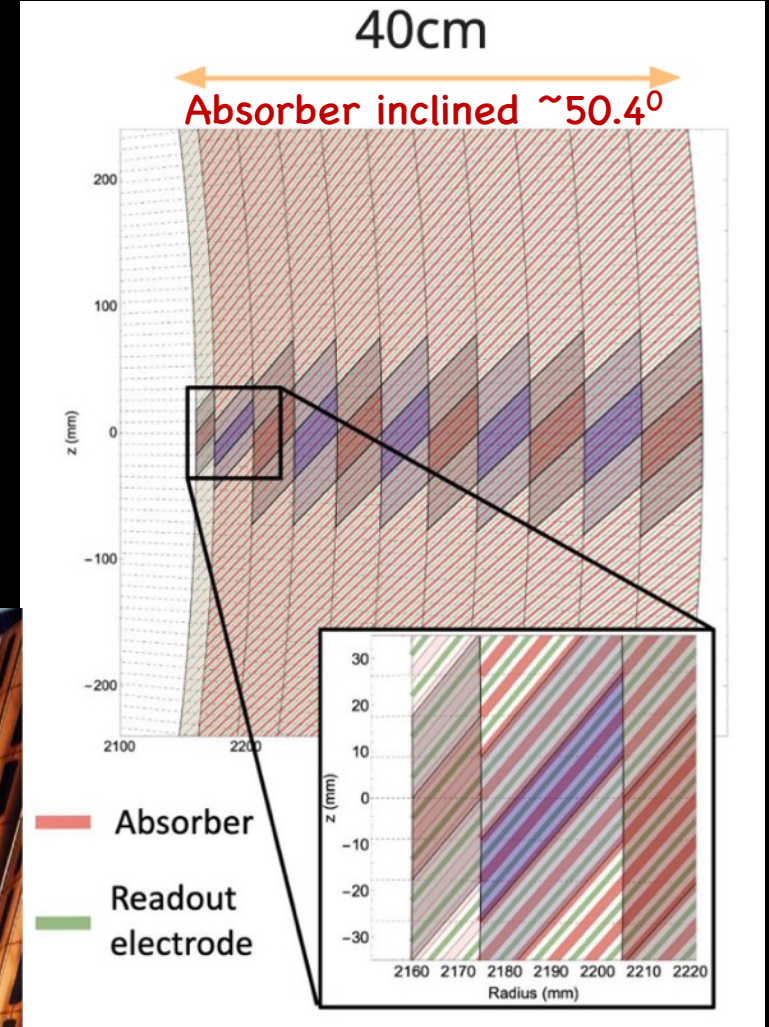
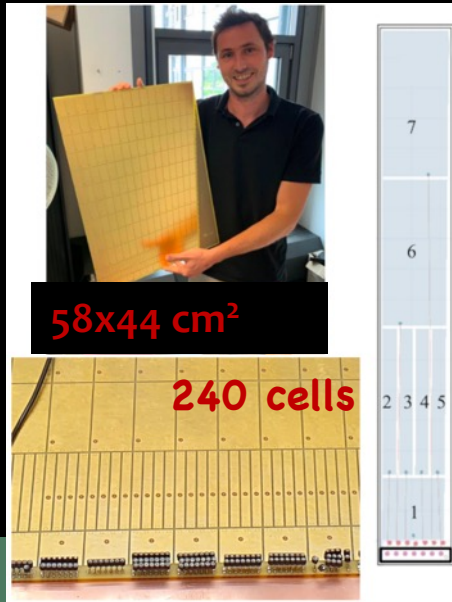
Absorber: Lead/Tungsten (2mm)
Sensor: LiAr(LiKr) (1.2-2.4mm)
Readout: Strips PCB
FCC-hh, FCC-ee

Based on LiAr ATLAS Calorimeter

Good energy resolution
(sampling term $\sim 10\%$)
Low systematics
PID Capabilities
Radiation hardness

Target 10-15 times higher granularity than ATLAS for PFA in high pile-up environment. (ATLAS Cu/Kapton electrode but PCB allows high granularity)

Multilayer
PCB developments



Low mass cryostats needed
CERN R&D: CFRP/Metal interfaces

SEP. 2024

OPTICAL BASED HOMOGENEOUS HIGH GRANULARITY EM CRYSTAL CALORIMETER - HGCCAL

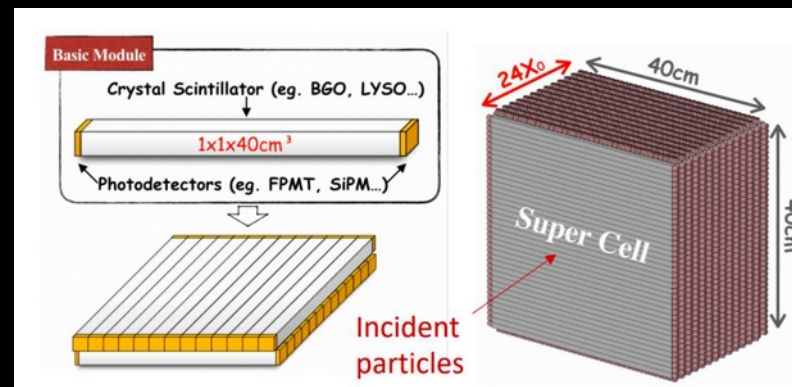
High density
Scintillating Crystal
(BGO/PWO)
Readout: SiPM
Higgs Factories

Design 1: Short bars

Small crystal cubes: fine segmentation longitudinal & transversal. → PFA

Single-ended readout SiPM

Design 2: Long bars



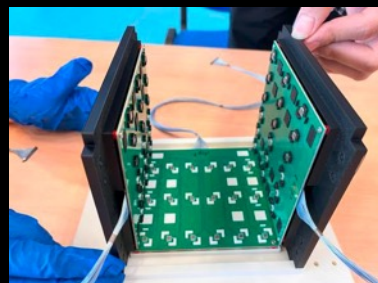
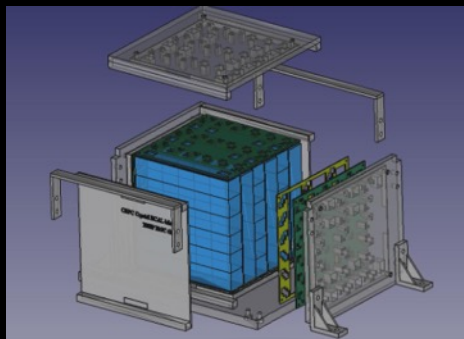
double-side readout SiPM with time
=> position along the bar

Less channels
reduce dead space

Ambiguities

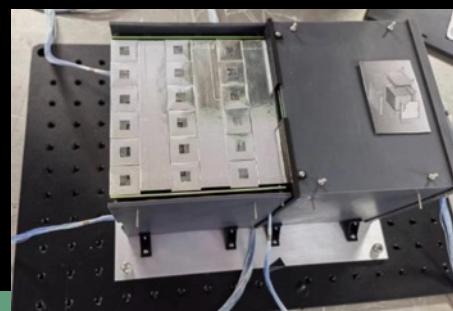
First Module

72 channels, $10.7 X_0$

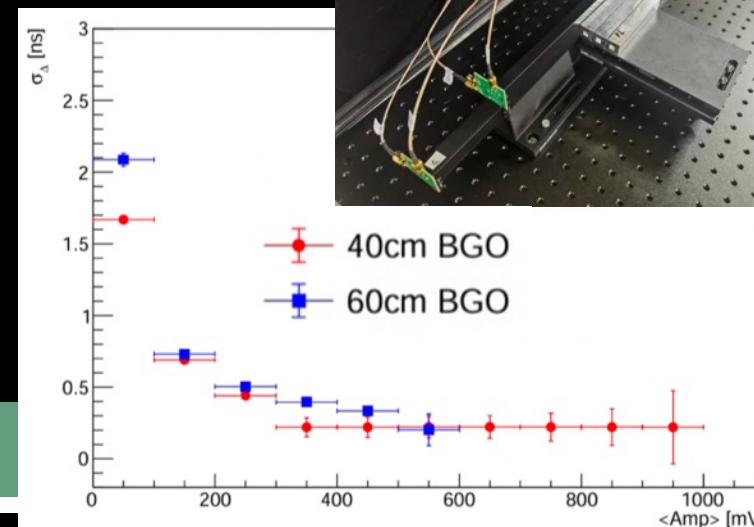
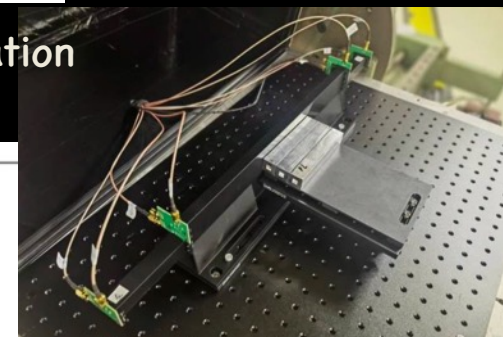


Second Module

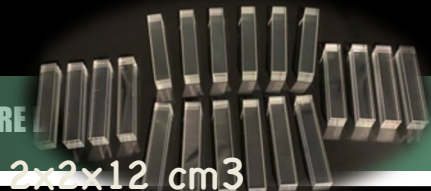
144 channels, $21.4 X_0$



Bars Time resolution
test set-up



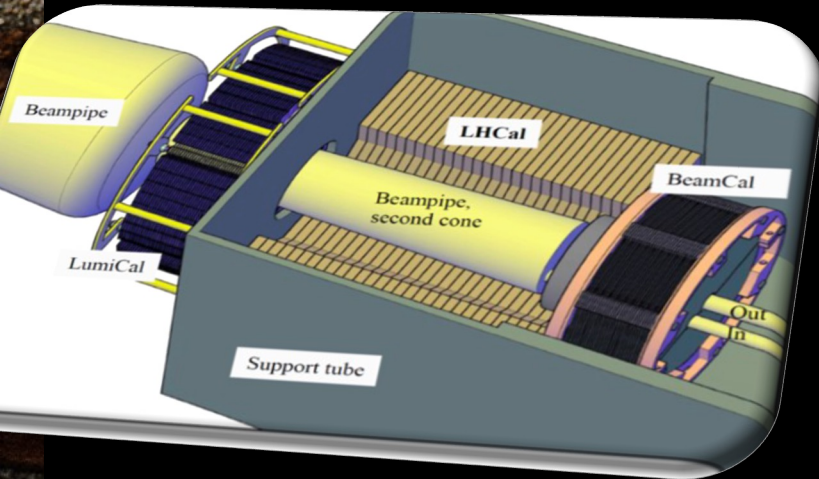
FUTURE



SILICON BASED SANDWICH CALORIMETERS FOR FORWARD CALORIMETERS

LC FORWARD CALORIMETERS

Similar still to be developed for FCCee



REQUIREMENTS

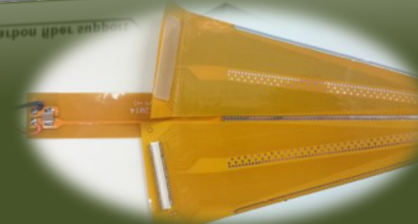
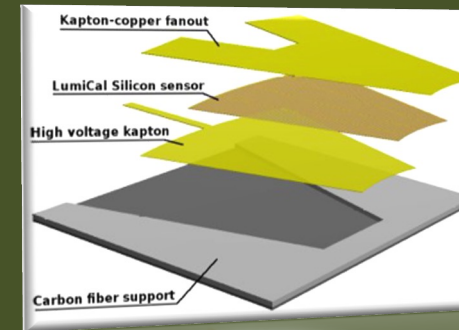
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- Fast readout
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very high radiation load (up to 1MGy/ year)
W + radiation hard sensors (GaAs, CVD Diamon, Sapphire)

LHCAL: Extends the calorimeter measurements to small polar angles
SiW or Si+iron

LumiCAL



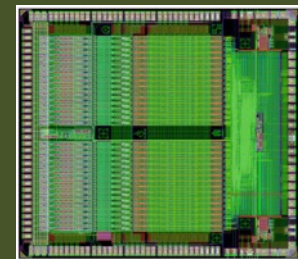
15 Detector planes
FLAME ASIC

2020 @ DESY

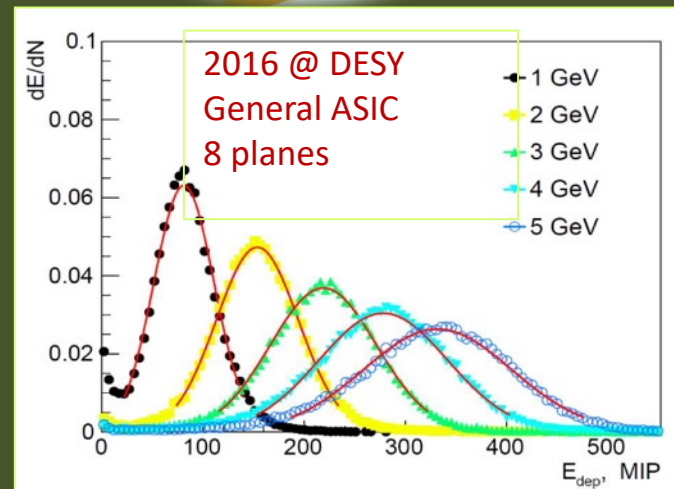


FLAME

FcaL Asic for
Multiplane
readout



3.7 x 4.3 mm²



A FAST SNAPSHOT ABOUT THE TYPE OF DETECTOR DEVELOPMENTS GOING ON IN SPAIN FOR FUTURE COLLIDERS

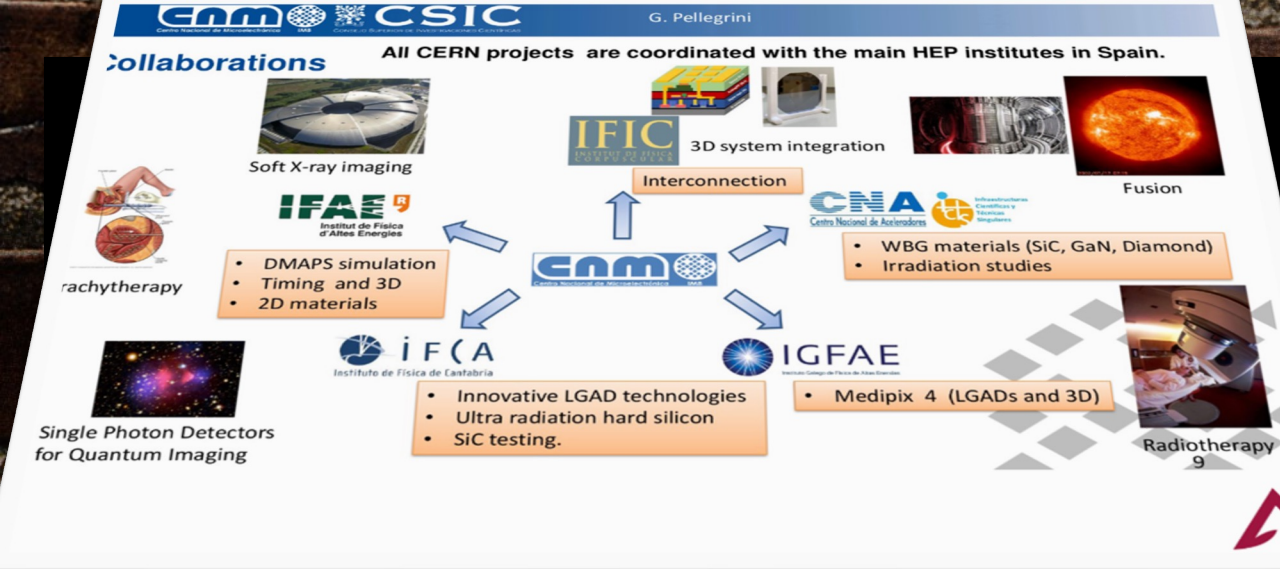
THE SPANISH COMMUNITY OF DETECTOR R&D FOR COLLIDERS HAS BEEN INVOLVED ON DETECTOR DEVELOPMENTS FOR

FUTURE $e+e^-$ SINCE AROUND 18 YEARS

MAIN CONTRIBUTIONS TO ILD DETECTOR (ILC AND NOW LOOKING ALSO FCC $_{ee}$) - LOI, DBD, TOP LEVEL COORDINATORS...

BUT ALSO AT CLIC

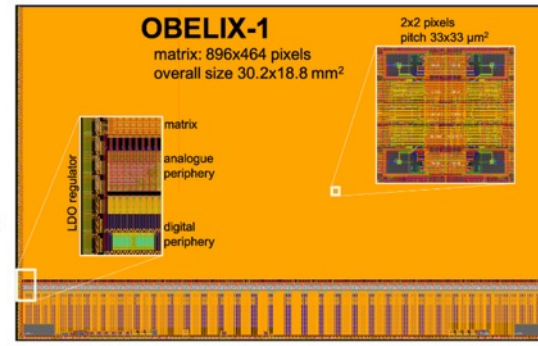
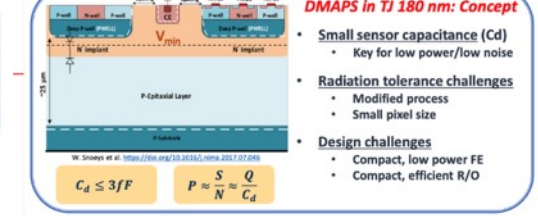
AND SOME GROUPS HAVE ALSO COLLABORATION WITH CEPC DIRECTLY OR INDIRECTLY



OBELIX – Layout



- Matrix inherited from TJ-Monopix2 developed for ATLAS (Tower 180 nm CIS)
- Dimensions adjusted to VTX geometry
464 rows and 896 columns, 29.60 x 15.33 mm² active area
- Low dropout regulators (LDOs) to allow a wide input supply voltage range 2-3 V
- Clock frequency for the timestamp and trigger unit is 21.2 MHz (timestamp length 47.2 ns)
- Trigger unit with 2-stage trigger memory (data loss < 0.02% at design trigger latency of 10 μs and hit rate of 120 MHz/cm²)
- 320 Mbit/s output



cmarinas@ific.uv.es

Participation of the Centro Nacional de Aceleradores (CNA) in CERN R&D collaborations on Semiconductor Detectors

RD50: "RADIATION HARD SEMICONDUCTOR DEVICES FOR VERY HIGH LUMINOSITY COLLIDERS"

- RD50: 65 institutes and 440 members

RD50 Project: "Thin Low Gain Avalanche Detectors (LGAD) characterization using Ion Beam Induced Charge (IBIC) and Time-resolved IBIC (TRIBIC) at the Centro Nacional de Aceleradores."

COLLABORATION: CNA, IFCA, CMM

LGAD:

- Moderate intrinsic gain.
- Higher bias → Higher gain.
- Ultrafast signal.

IBIC/TRIBIC powerful tool for semiconductor characterization

From 2024:
ECFA Roadmap →
New 'Detector R&D' collaborations →

- DRD3: Solid-State detectors
- 143 institutions / 600++ people
- WG5: Characterization techniques, facilities

CNA FACILITIES

3 MV Tandem Ions: H-Au 600 keV-few MeV

Cyclotron 18 MeV H⁺/ 9 MeV D⁺

CNA contact: Carmen Jiménez-Ramos (mcyjr@us.es)



Upgrade

CMOS & LGADS

SEP. 2024

Si ECAL hybridization / integration

SILICON DETECTORS FOR CALORIMETRY

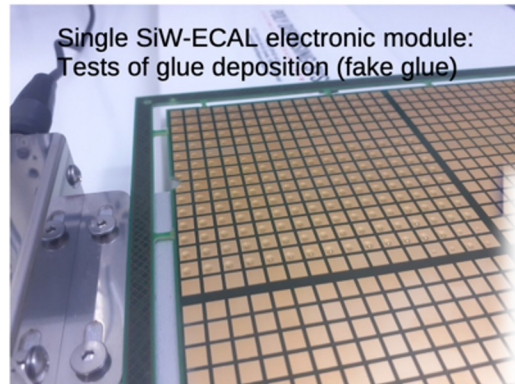
Common R&D Short term

▷ Current technological prototype solution for sensor-PCB connection is based on epoxy-silver glue.

- Mechanical strength, industrialization, durability, aging studies,...
- Silver → may be an issue on high radiation environments



Single SiW-ECAL electronic module



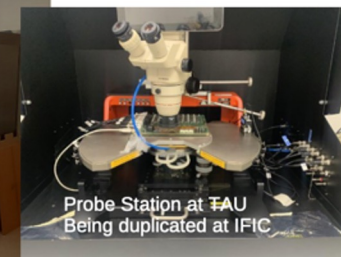
Single SiW-ECAL electronic module:
Tests of glue deposition (fake glue)

IFIC-Lab for ECAL hybridization

- ▷ **New facility and capabilities at IFIC**
- ▷ **Funding: CIDEAGENT/ASFAE/CNS** → In line with ECFA – R&D roadmap, DRD6, Future Colliders
- ▷ **IFIC will become** the hub for module hybridization R&D / production / commissioning for DRD6 Si-ECALs and for the LUXE experiment



New installation at IFIC
(to be finished in March/Abril May/June 2024)



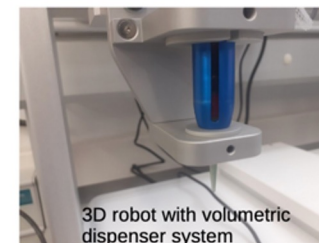
Probe Station at FAU
Being duplicated at IFIC



Dry cabinet,
curing oven



Tooling and tests of mixed
hybridization → silver-
epoxy and ultra-thin tape

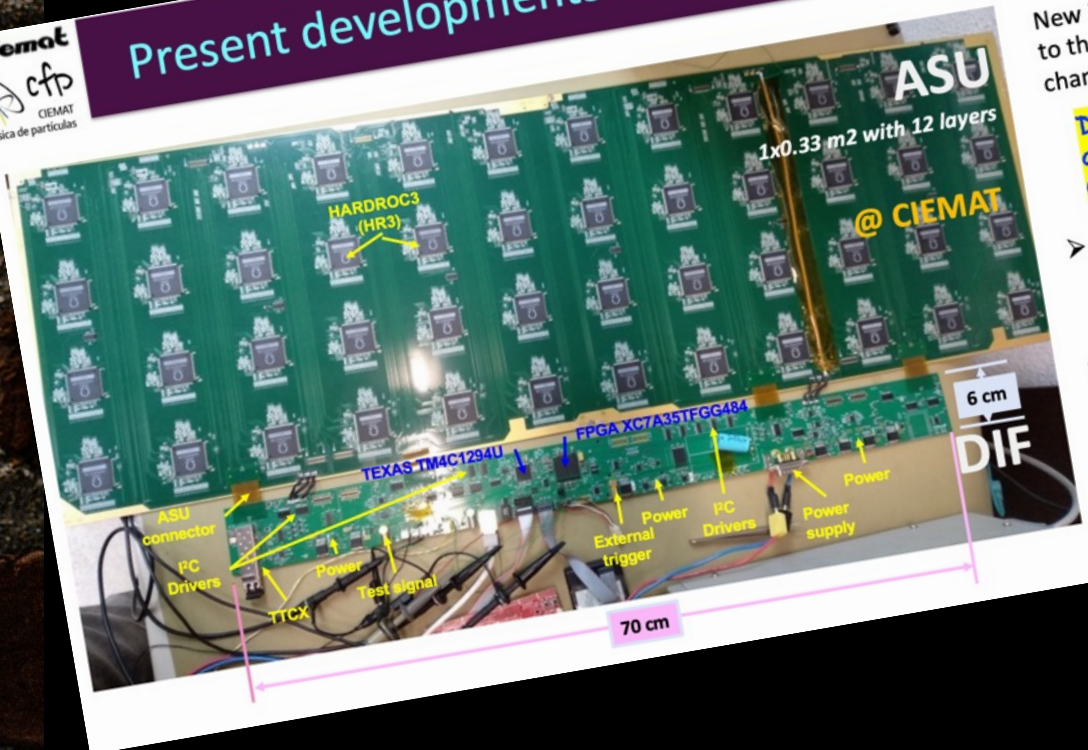


3D robot with volumetric
dispenser system



Tooling and tests of
hybridization with silver-epoxy

Present developments and future evolution: Electronics



New DIF capable to handle up to the 30000 readout channels of a 3x1m² RPC

Designed, produced and tested by CIEMAT

- Now under DAQ in coll the Lyon
- To be beam



4. ITA's activities in future Accelerators

ITA's activities focus on three areas: power distribution, FEE design and noise characterization

Characterisation of graphene-based supercapacitors for pulsed power applications

Power distribution

efficiency (%)
iRef = 7.5A
deadtime = 25ns

GaN based DC-DC converters design for low power applications

Noise characterization

Noise characterization system for physics detectors

ROC power stage design - RD53

FEE design

High density interconnect board design - Flex PCB

CALORIMETRY

ELECTRONICS

ADVANCED MECHANICS

Forward tracker

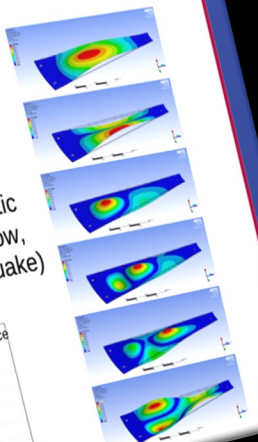
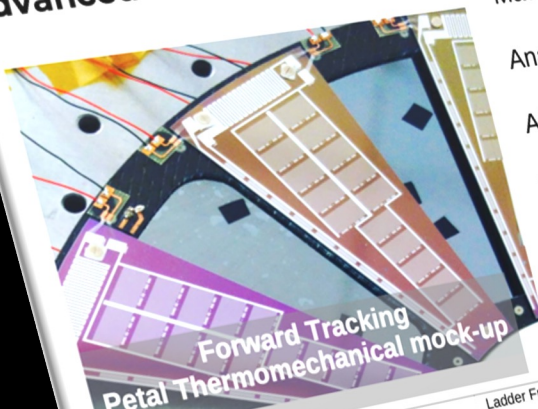
Calorimetry

Vibration analysis: advanced mechanics (AIDA2020-AIDAInnova)

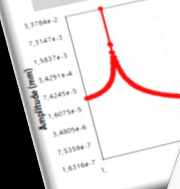
Master's thesis Yamal Naser Requena

- Analytical expressions
- ~ ANSYS FEA
- ~ Measurements

Extend to more realistic vibration loads (air flow, cavern floor, earthquake)



Ladder Frequency response to a 1e-5N periodic force

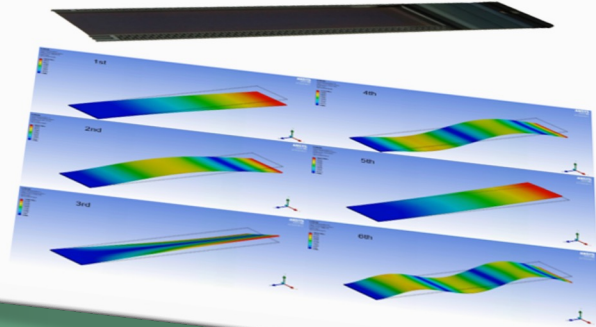
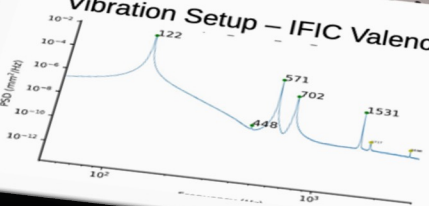


Forward Tracking: advanced mechanics (AIDA2020-AIDAInnova)

Multiple silicon structures measured in Oxford and Valencia



Vibration Setup – IFIC Valencia



1m3 SDHCAL Construction

Assembly of Mechanical Structure

GRPC insertion

Special table with machined guide lines

Rotation tool

1m3 SDHCAL mechanical structure

EBW final assembly

5 plates 3x1m²

Welding zones

Development of Electron Beam Welding assembly protocols to reduce deformations introduced by welding procedures below mm level (600 microns in this test with 5 plates 3x1 m²)

IN SUMMARY....



IN SUMMARY....



**BUT THERE IS PLENTY OF WORK AND FUN
IN FRONT !!**



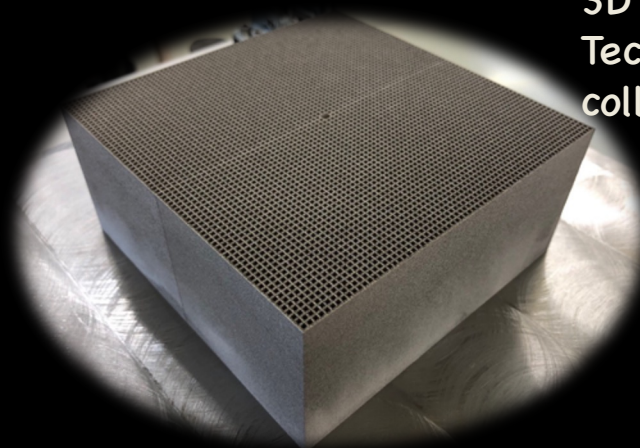
BACKUP

OPTICAL BASED SPACAL CALORIMETER: PicoCAL

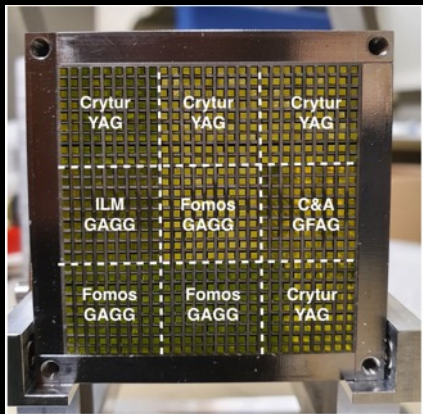
PicoSecond SPACAL

Absorber: Lead or Tungsten
 Sensor: Radiation hard Scintillator Fibers
 Readout: Light guides
 Fast photo detectors: MCD PMTs/SiPM
 LHCb, Higgs Factories FCC-hh

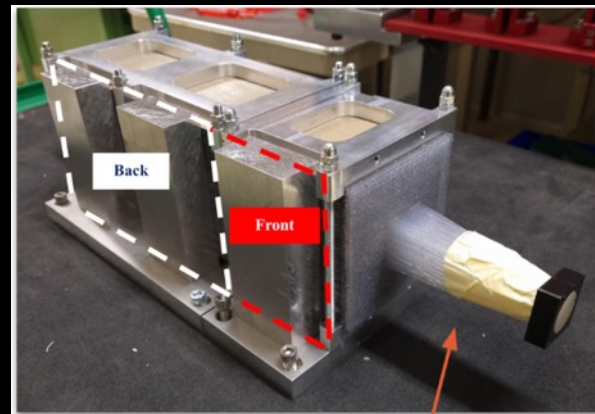
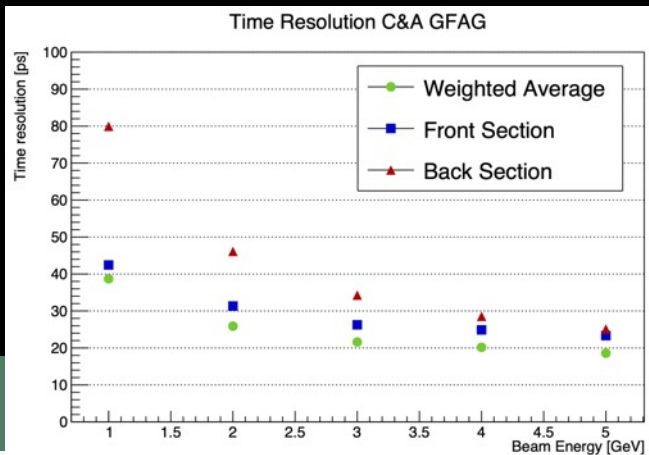
3D printed tungsten absorber
 Technical development in
 collaboration with industry



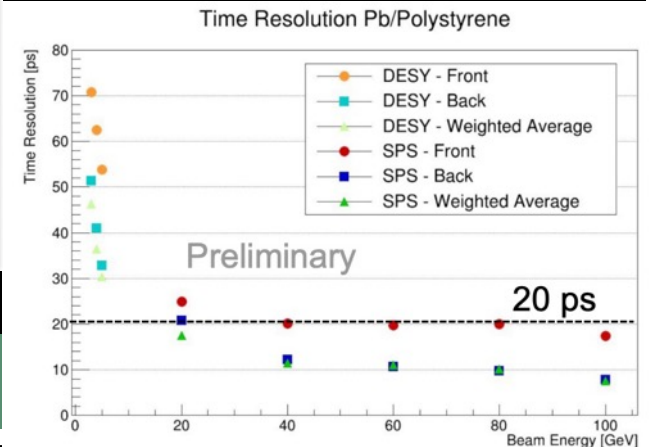
12x12 cm²



Garnet Crystal fibers + Tungsten



Polystyrene fibers + lead



OPTICAL BASED SHASLIK-LIKE CALORIMETER GRAINITA

Inorganic crystals have excellent energy resolution but expensive, limited granularity
Sampling calorimeters worst resolution due sampling fraction

Scintillator grains in transparent liquid
Readout: WLS fibers
- SiPM
Higgs Factories

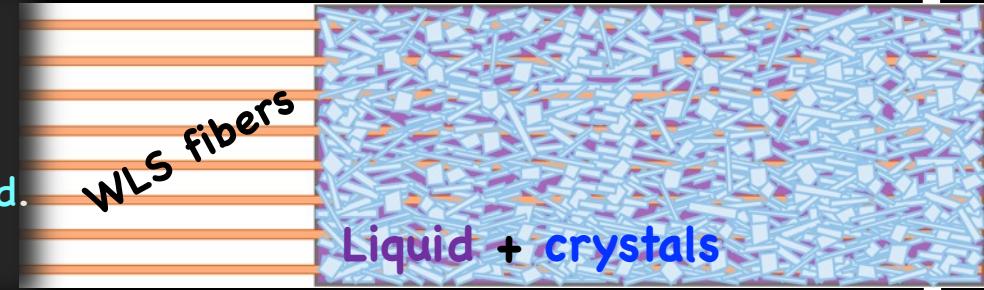
GRAINITA:

High Z scintillator sub-millimetric inorganic scintillator crystals in a bath of high-density liquid.

Light collection by WLS fibers, as shaslik

Scintillator candidates:

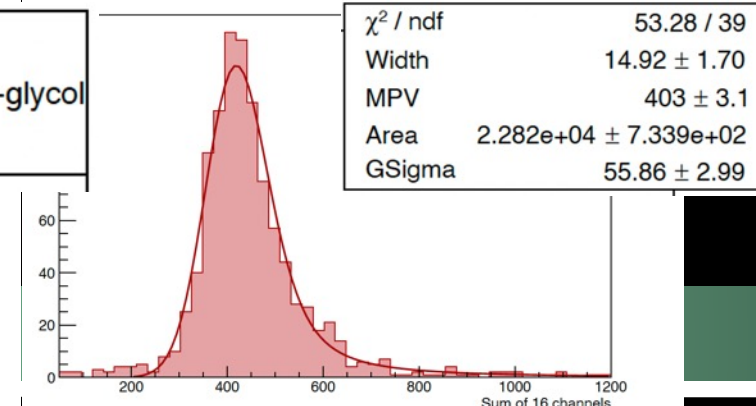
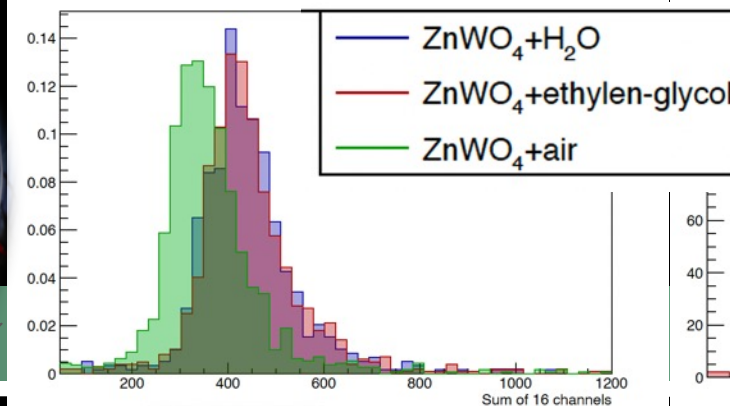
- ZnWO₄ grains (spontaneous crystallization method)
- BGO crushed crystals



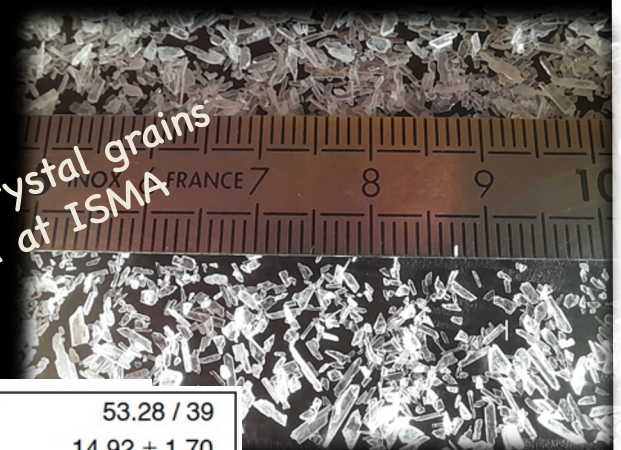
16 channel prototype

Cosmic tests Set-up

Cosmic tests results - ZnWO₄ + different liquid



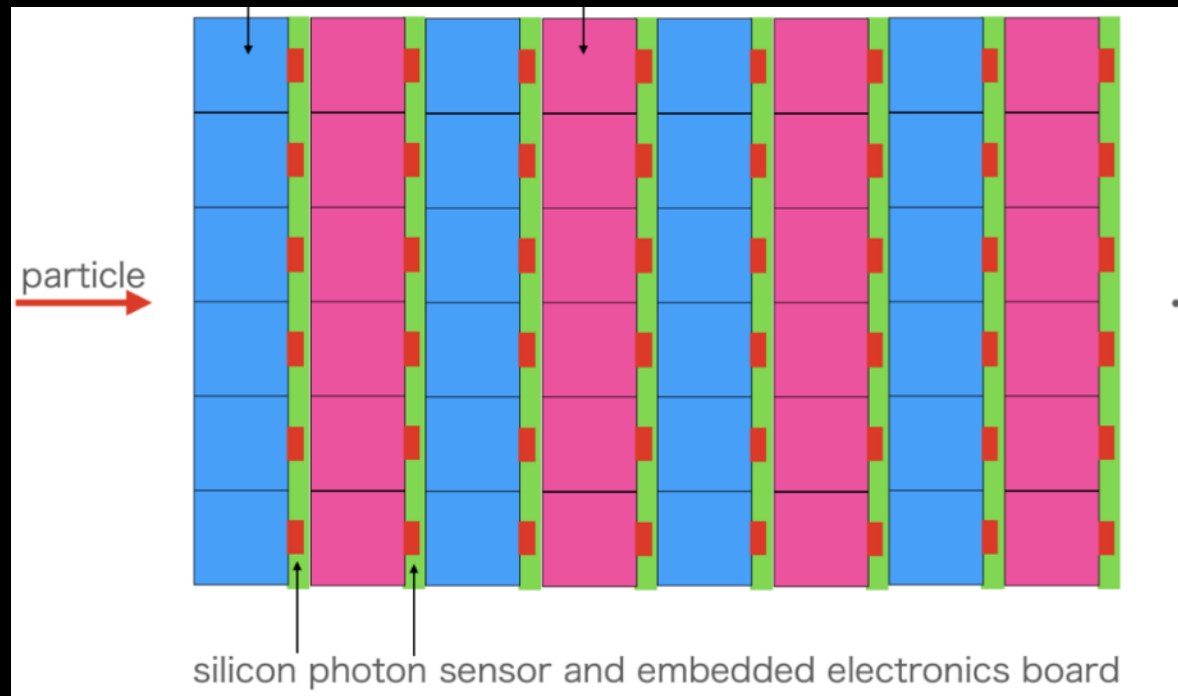
ZnWO₄ crystal grains produced at ISMA



DOUBLE READOUT SANDWICH CALORIMETER

Higgs Factories

Alternating layers of **heavy scintillator** (e.g. PWO) and Cherekov medium (lead glass)
Readout by embedded **electronic board** with SiPMs



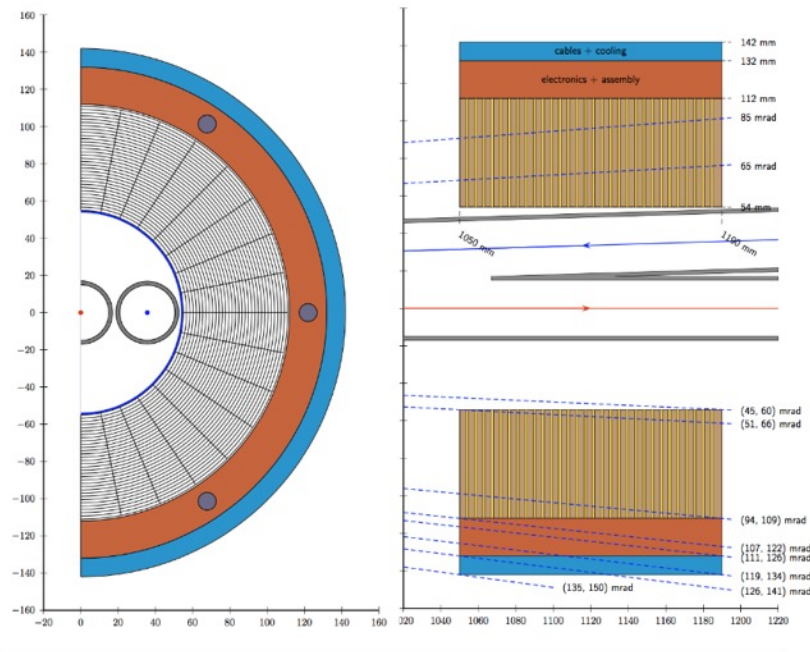
Status

Simulations & individual
crystal material R&D

The luminosity monitor

- Design largely inspired from FCAL study for linear colliders
 - ◆ Same geometry works: "just" make it smaller and closer to the IP
 - Centred around the outgoing beam (measures the outgoing particle deviation)

- + Length 10 cm (1.05 to 1.15m)
- + Radius from 5.4 to 14.2 cm
- + 30 layers ($1X_0$) of 3.5mm W + 1mm Si
- + 32×32 Si pads in (r, ϕ) : 3×10^4 channels
- + Mechanical support on FF system
- + Total Acceptance: 45-95 mrad
- + Loose acceptance: 63-83 mrad
- + Tight acceptance: 68-78 mrad
- + $\sigma(e^+e^- \rightarrow e^+e^-) = 6-13$ nb
- + Statistical precision on luminosity:
 - Few 10^{-5} at the Z pole
 - Few 10^{-4} at the $t\bar{t}$ threshold
- + Positioning of the two front faces with $1\mu\text{m}$ precision (fixed to the BP)



Patrick Janot

Séminaire au CPPM
26 Feb 2018

24